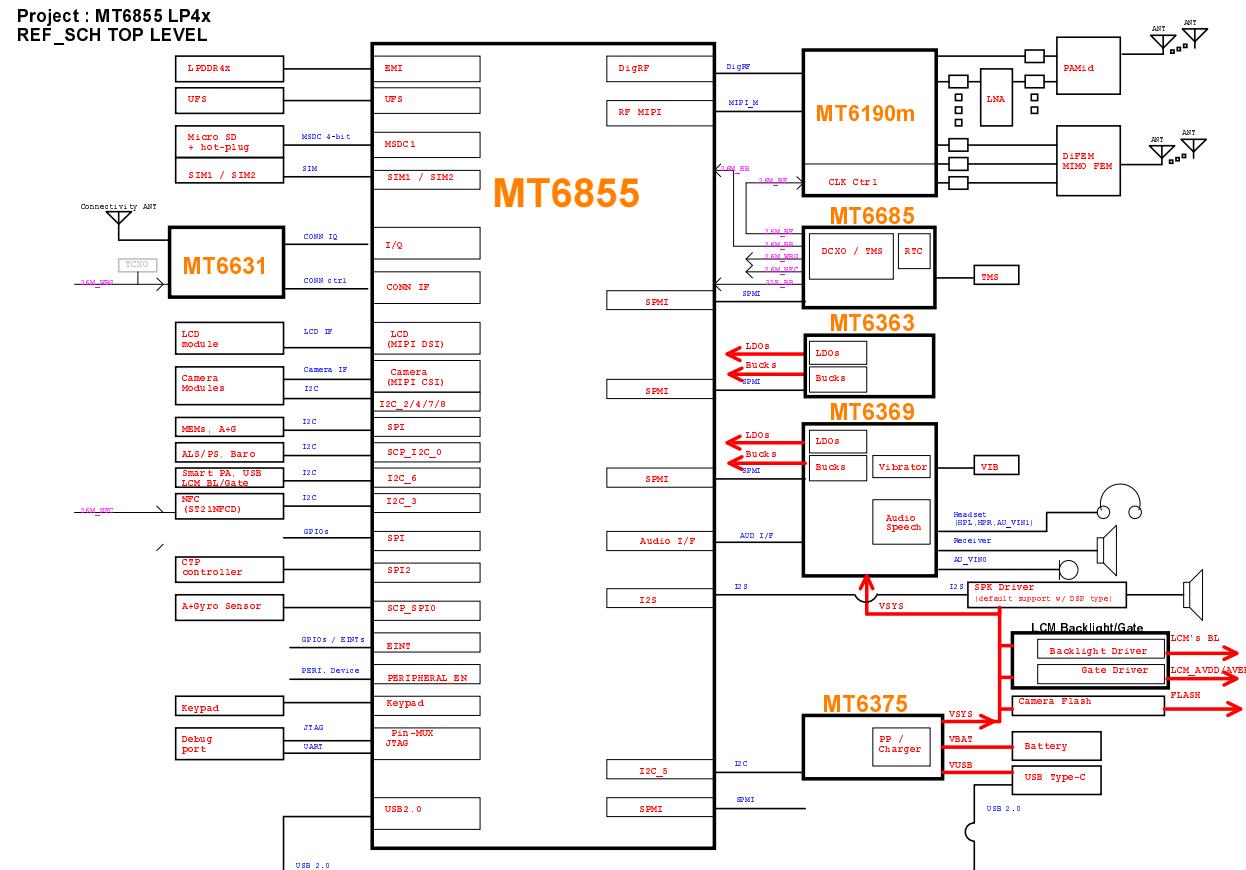


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03_I2C_ID_Overview	33_Flash_LED	66.NFC_PN553
04_Change_Note	34_FingerPrint	
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06_BB_POWER_PDN	36_SIM/SD_IF	
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12_BB_AUXADC_Thermal		
13_POWER_MT6359-Buck		
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17_POWER_MT6315		
18_POWER_MT6315_VMD		
19_POWER_MT6360_BUCK_LDO		
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21_POWER_MT6360_Charger		
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29_Battery/Sidekey		
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	44.APT/ET_Module_1	
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	60.Antenna_5_DRX_LMHB	
	61.Sar_sensor_SX9338IULTRT	
	62.WCN_IC_Power_GND	
	63.WCN_RF0_ANT3	
	64.WCN_RF1_ANT4	

02_Block_Diagram



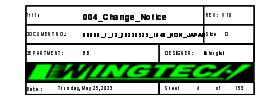
03_I2C_ID_Overview

I2C	AP,SCP,SSPM	Function	I2C/I3C Spec.	I2C Slave Address (7-bit mode)
I2C-0			I2C	
I2C-1	SCP	M Sensor	I2C	MMC5603NL I2C address: 0x0C (Read:0x61 Write:0x60)
		ALS+PS Sensor		AK08918C 0x46 I2C address: 0x46 (Read:0x19 Write:0x18)
I2C-2	AP	Main CAM **M	I2C	HII336 I2C address: 0x1A (Read:0x41 Write:0x40) ; OV13B I2C address: 0x6C (Read:0x6D Write:0x6C) ; IMX258 I2C address: 0x50 (Read:0x21 Write:0x20) S5K3L6 I2C address: 0x50 (Read:0x21 Write:0x20)
I2C-3	AP	NFC	I2C	A96T346DFP I2C Address 0x20 (Read:0x41 Write:0x40)
		SAR		
I2C-4	AP	Front Camera	I2C	S5K4H7 I2C Address : (Read:0x5B Write:0x5A) H646 I2C Address : (Read:0x41 Write:0x40) GC8054 2C Address : (Read:0x6F Write:0x6E)
		Macro 2 M CAM		GC2375 I2C Address (Read:0x2F Write:0X2E) OV02A10 I2C Address (Read:0x7B Write:0x7A)
I2C-5	AP	MT6360	I2C	MT6360 PDs I2C address: 0x4E (Read:0x6D Write:0x6C) MT6360 PMIC's I2C address: 0x1A (Read:0x35 Write:0x34) MT6360 PMU's I2C address: 0x4 (Read:0x69 Write:0x68) MT6360 LDO's I2C address:0x64 (Read:0x99 Write:0xC8)
I2C-6	AP	SmartPA	I2C	AW68264CSR Speaker AMP I2C Address: 0x34(Read:0x69 Write:0x68)
		LCM Gate Driver		S5M108 I2C address:0x3E (Read:0x7D Write:0x7C)
		LCM BACKLIGHT		AV99703 I2C address:0x36 (Read:0x6D Write:0x6C)
I2C-7	AP		I2C	TBD
I2C-8	AP	Depth 2 M CAM	I2C	OV02B1B I2C address: (Read:0x78 Write:0x79)
				GC2375B I2C address: (Read:0x2F Write:0x2E)
I2C-9	AP		I2C	

Note : I2C Spec.: Standard mode (100 kbps) and Fast mode (400 kbps), Fast mode Plus (1 Mbps) and High-speed mode (3.4 Mbps)

04_Change_Note

Date	Version	Page	Change notice
20120.10.15			Changed from 5G-C HW
20120.10.16			1st release

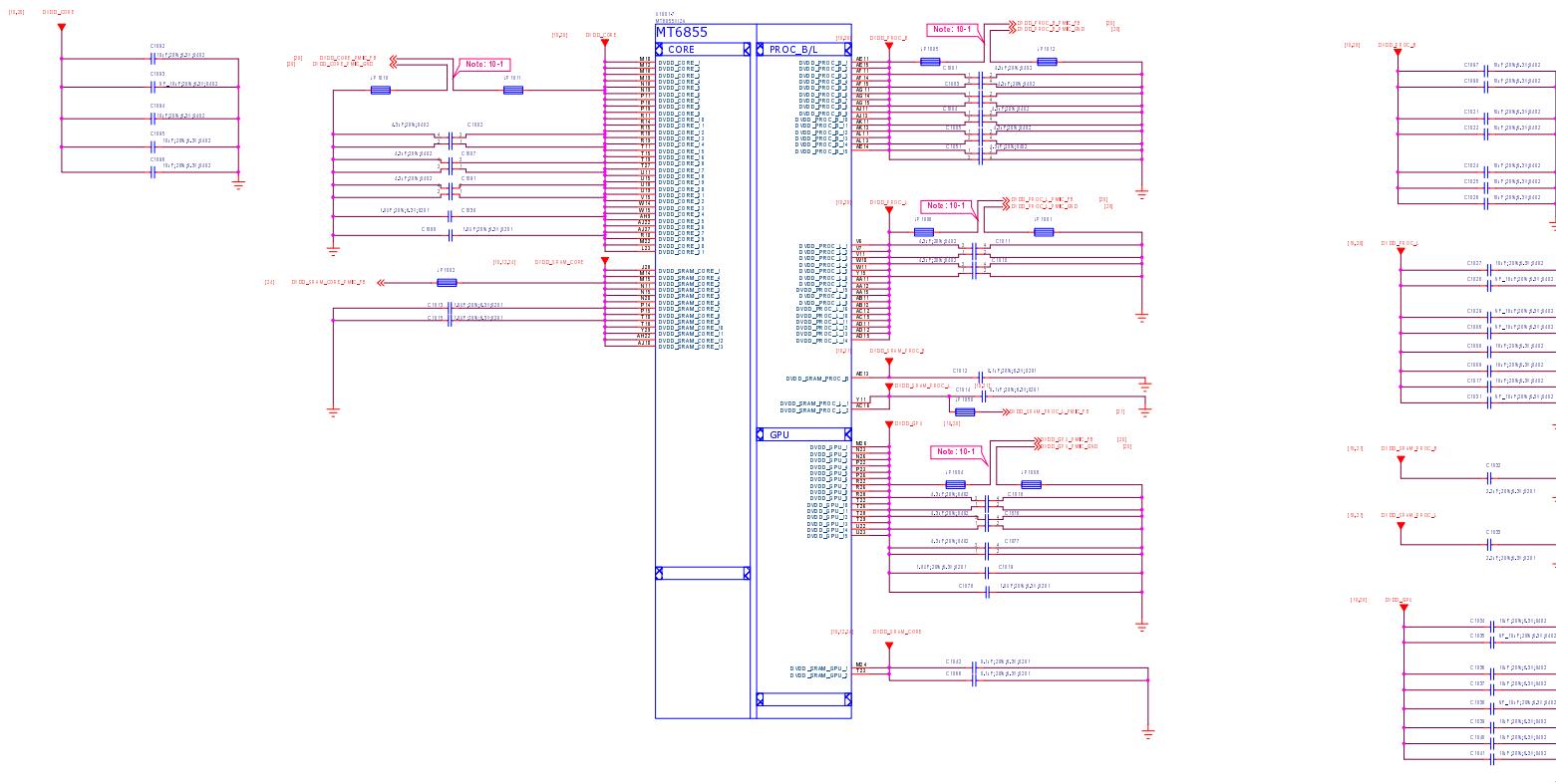


10_BB_POWER_PDN

Schematic design notice of "10_BB_POWER_PDN" page.

Note 10-1: Differential pair of PMIC remote sense must be close to BB's ball.

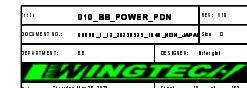
Remote sense trace with GND shielding to PMIC (Differential)



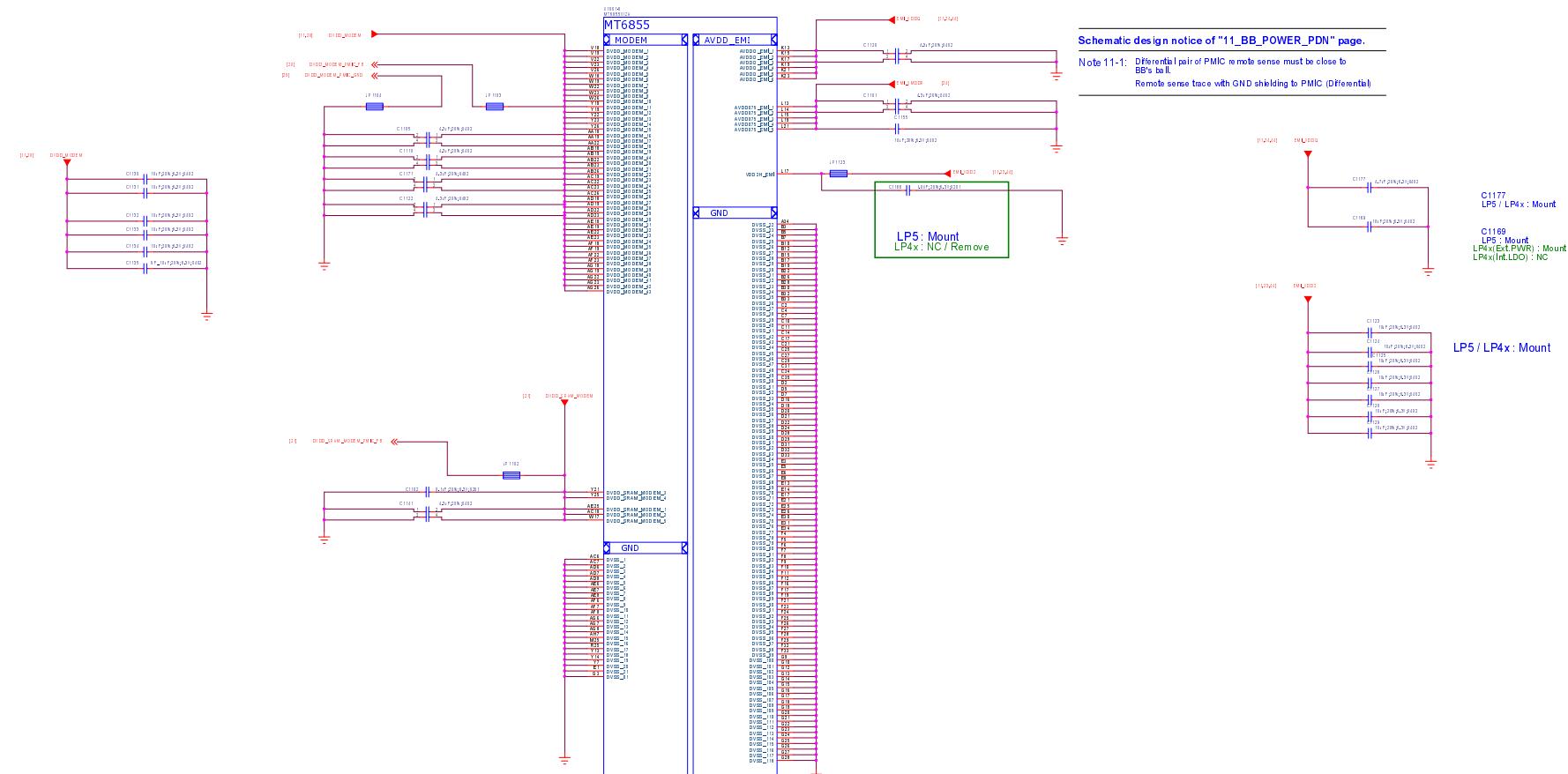
Schematic design notice of "10_BB_POWER_PDN" page.

Note 10-1: Differential pair of PMIC remote sense must be close to BB's ball.

Remote sense trace with GND shielding to PMIC (Differential)

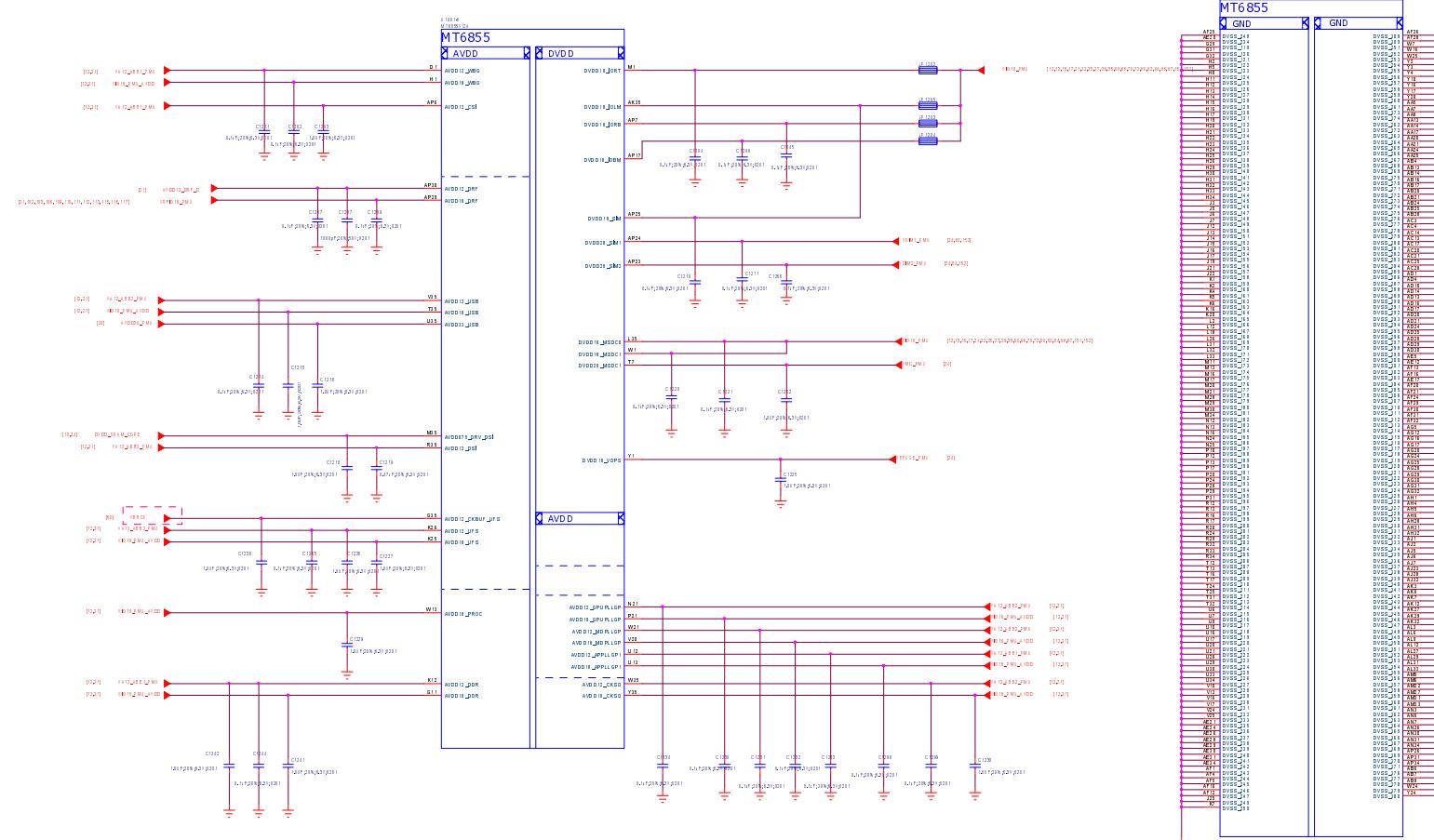


11_BB_POWER_PDN



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Doc. Mktg. No.:	XXXXXX	Doc. Rev.:	0
Off. Rev. No.:	02	Off. Date:	01/01/01
WINGTECH	Printed Date:	2021/01/01	Sheet:

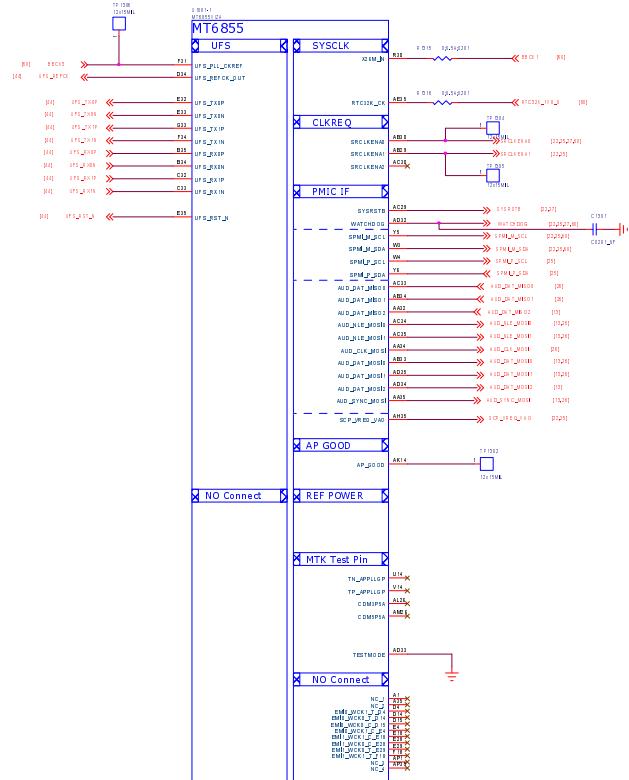
12_BB_POWER_IO



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Comments:	00	Design Date:	00/00/0000
Created:	00/00/0000	Last Update:	00/00/0000

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13_BB_1



Schematic design notice:

Note 13-1: The load cap. have to be placed as close to REFP ball as possible.

Note 13-2: "AUD_DAT_MOSI0" and "AUD_DAT_MOSI1" pin features in strapping pin to enable JTAG.

AUD_DAT_MOSI0	AUD_DAT_MOSI1	AP JTAG	IO JTAG	DAP_SONIC/DAP_MD32
L (Default)	L (Default)	N/A	N/A	
L (Default)	H (by external PU)	SPB_CSB, SPB_CLK, SPB_M0, SPB_M1, KPCOL	N/A	N/A
H (by external PU)	L	SPB_CSB, SPB_CLK, SPB_M0, SPB_M1, KPCOL	EINT[8:12]	SPB_CSB, SPB_CLK, SPB_M0, SPB_M1
H (by external PU)	H (by external PU)	EINT[8:12]	N/A	N/A

Note 13-3: "AUD_DAT_MOSI2" pin features in strapping pin to booting (eMMC/UFS).

AUD_DAT_MOSI2	Storage Booting
L (Default)	Only UFS boot
H (by external PU)	Only eMMC boot

Note 13-5: "AUD_DAT_MISO2", "AUD_SYNC_MOSI" and HW strapping pin to enable DDR.

AUD_DAT_MISO2	AUD_SYNC_MOSI	DDR Type
L	L	LP4x MCP
H (by external PU)	L	LP5 MCP
L	H (by external PU)	LP4x DSC
H (by external PU)	H (by external PU)	Reserved

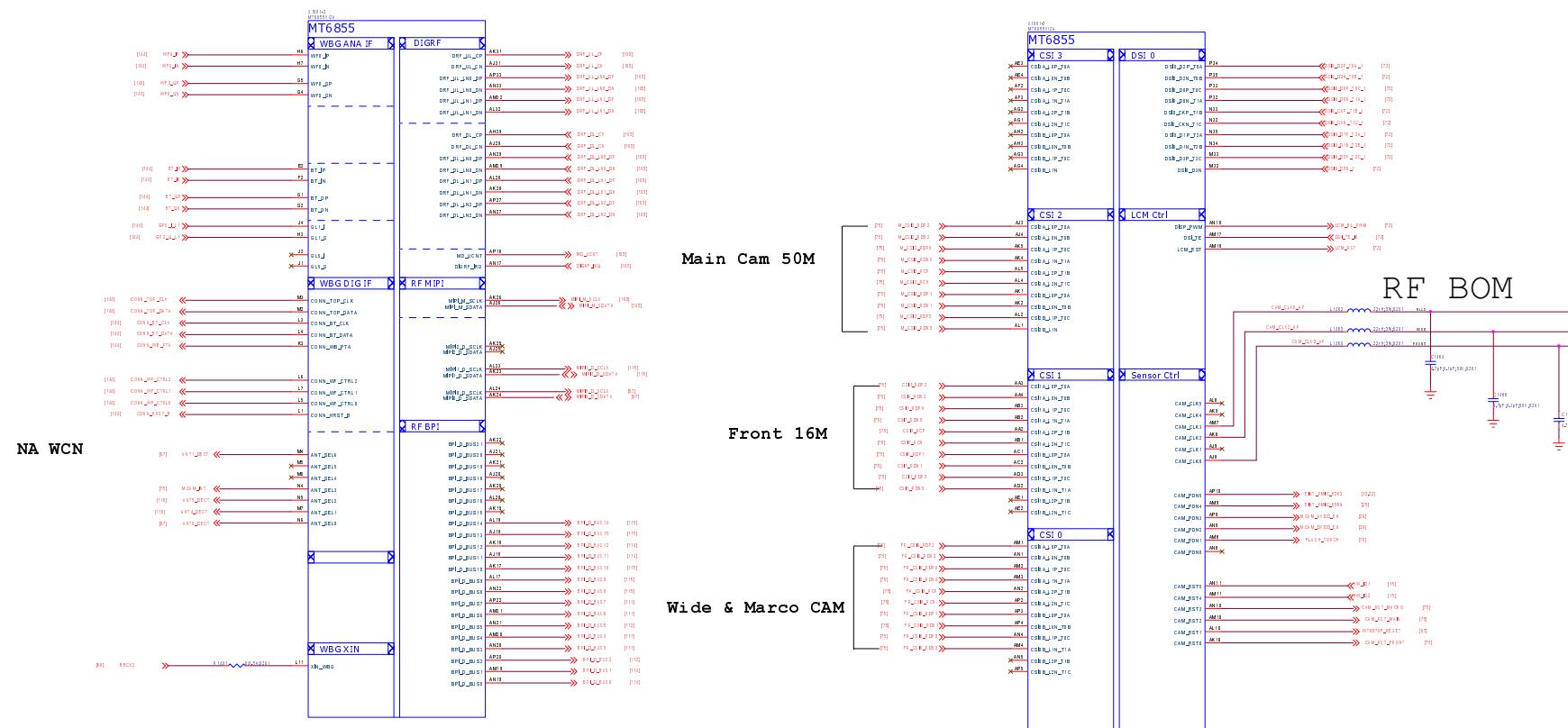
Note 13-6: "EINT_PMIC_6363" is strapping pin to select VEMC Voltage.

PMIC6363's EINT	VEMC	Application
L	2.5xV	UFS 3.1
H (by external PU)	3.0V	UFS 2.x

Note 13-7: General MT6369 DRAM selection HW STRAPPING

AUD_NLE_MOSI0	AUD_NLE_MOSI1	MT6369_EXT_EN	DRAM PWR	MT6369_VMDDR	MT6369_VMDQ
L	L	OFF	LP4x	0.75V	0.8V
L	H	ON (for LP4x VDDQ, option.)	LP4x	0.75V	OFF
H	L	ON (for LP5 VDDQ)	LP5	0.75V	OFF
H	H	ON (for LP5 VDDQ)	LP5	0.75V	OFF

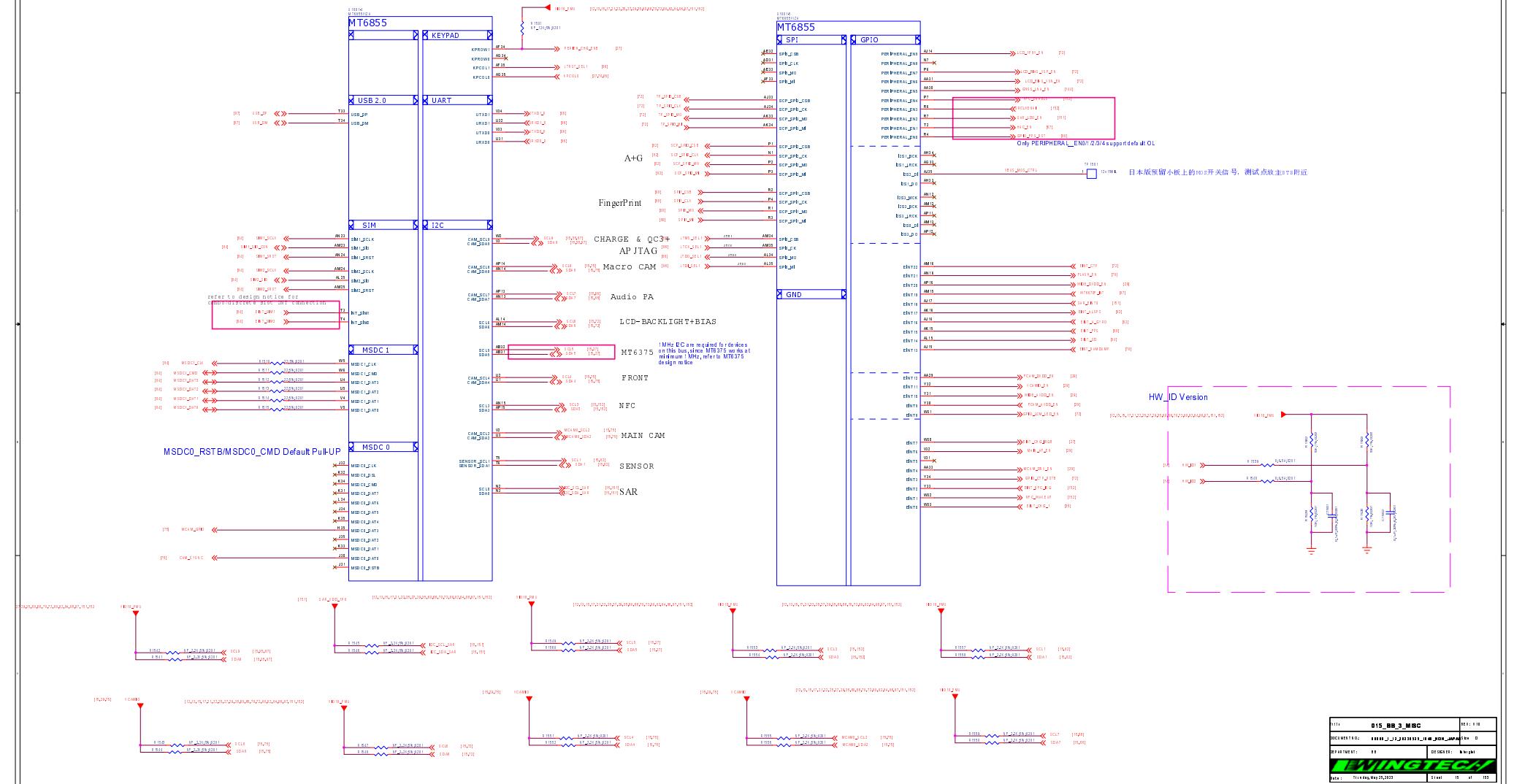
14_BB_2



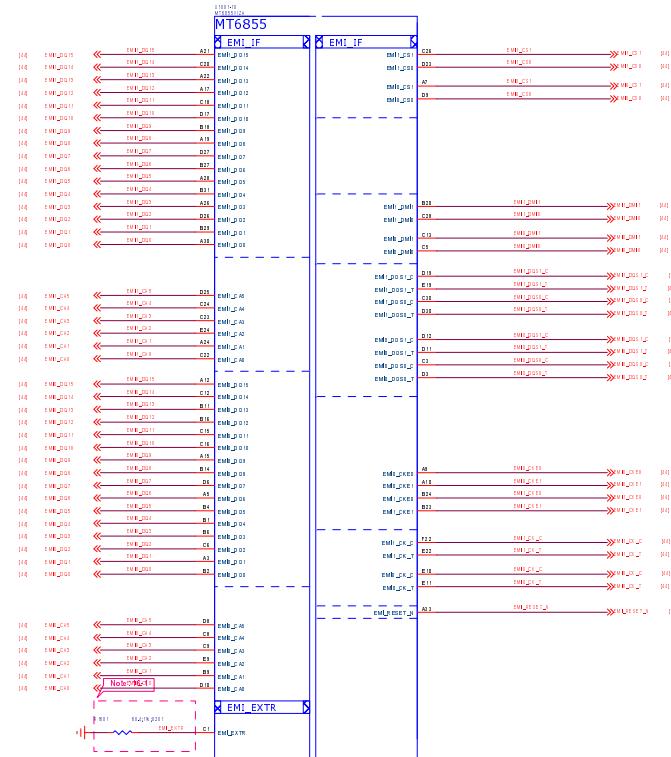
close the SoC

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Comments:	BB	Date:	Initial
Author:	TECHNICAL DESIGNER	Sheet:	10 of 102

15_BB_3



16_BB_4

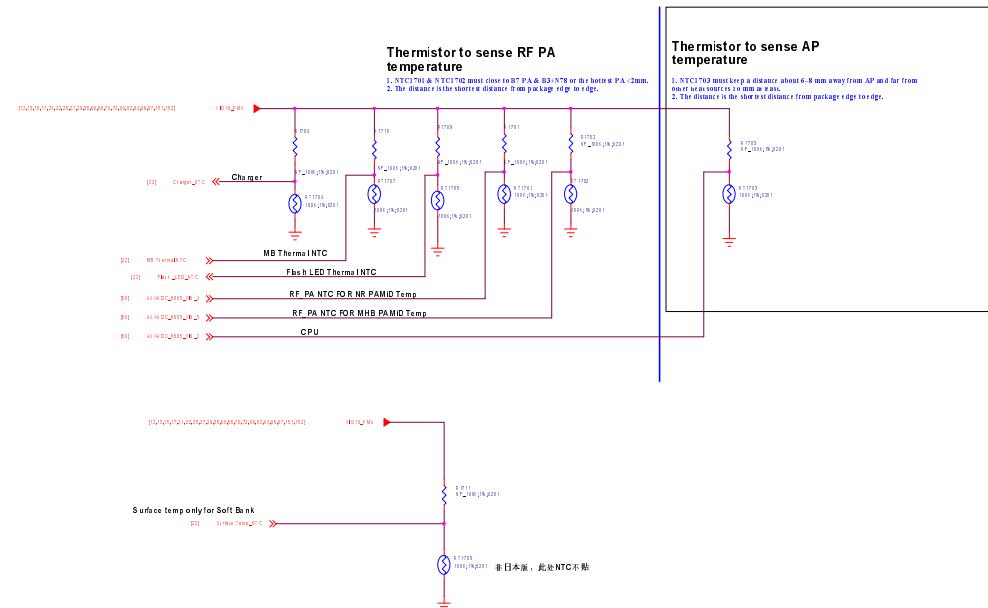


Schematic design notice of "16_BB_4_Interface" page:

Note 16-1: R4001 please select 60.4 ohm (1%) resistor

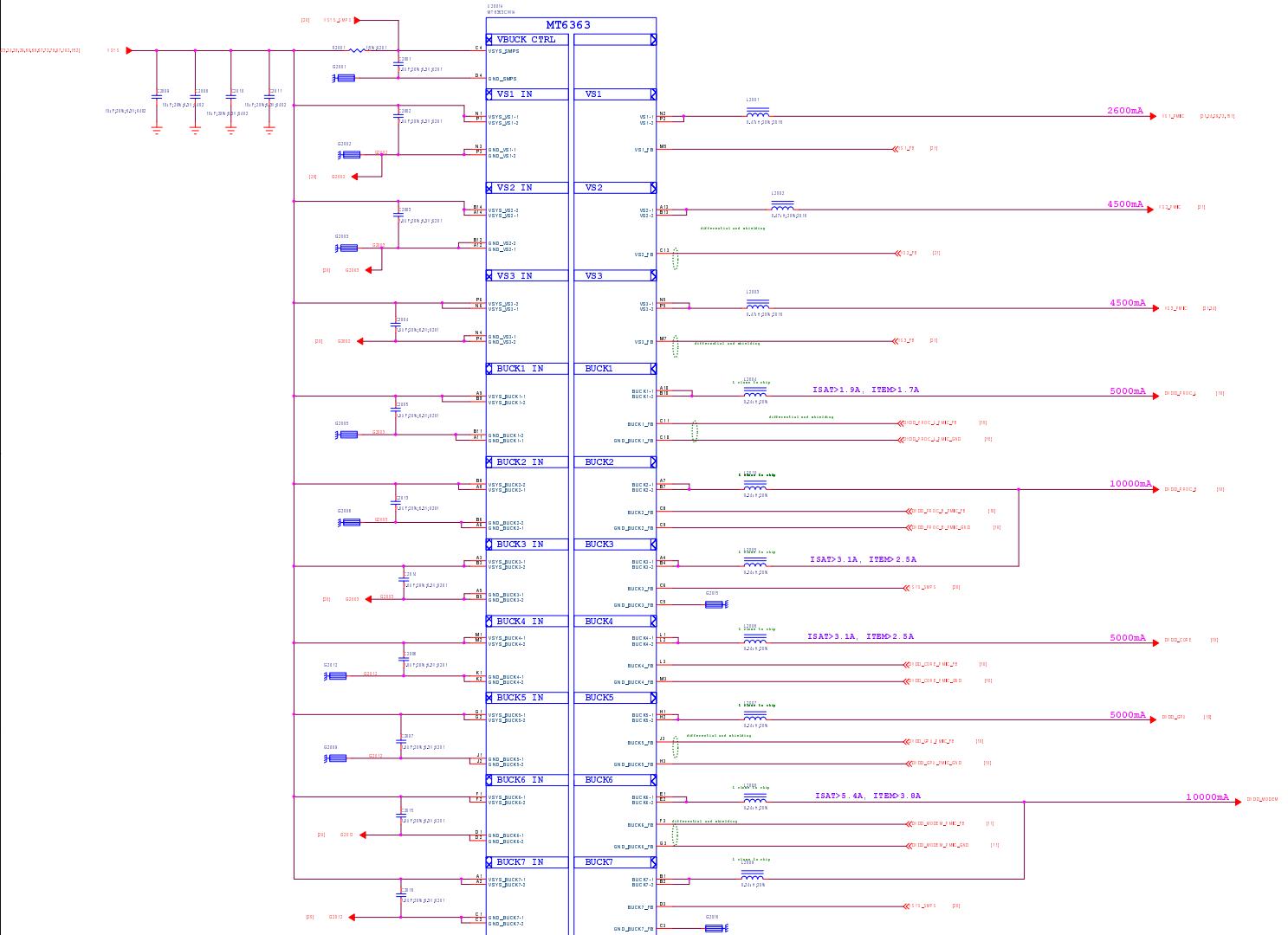
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Document No.:	00000000000000000000000000000000	Date: 00/00/0000
Department:	BB	Design: Design
WINGTECH		Page: 10 of 102

17_BB_AUXADC_Thermal



File:	017_BB_AUXADC_Thermal	Page:	1/1
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Department:	BB	Design Date:	2014-01-01
WINGTECH		Rev:	0

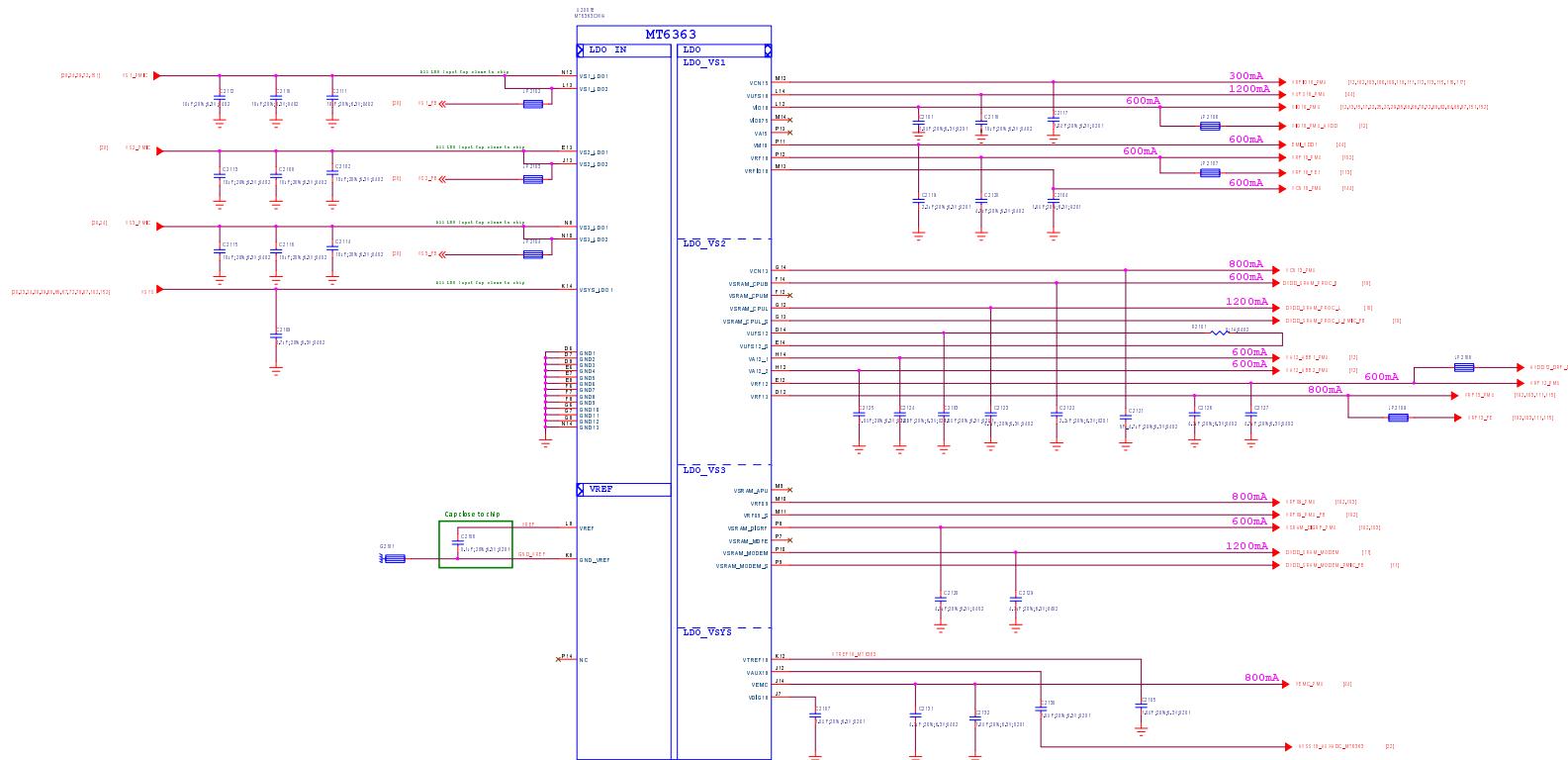
020_POWER_MT6363_Buck



020_POWER_MT6363_BUCK	020
020_M110_VS1	020_VS1
020_M111_VS2	020_VS2
020_M112_VS3	020_VS3

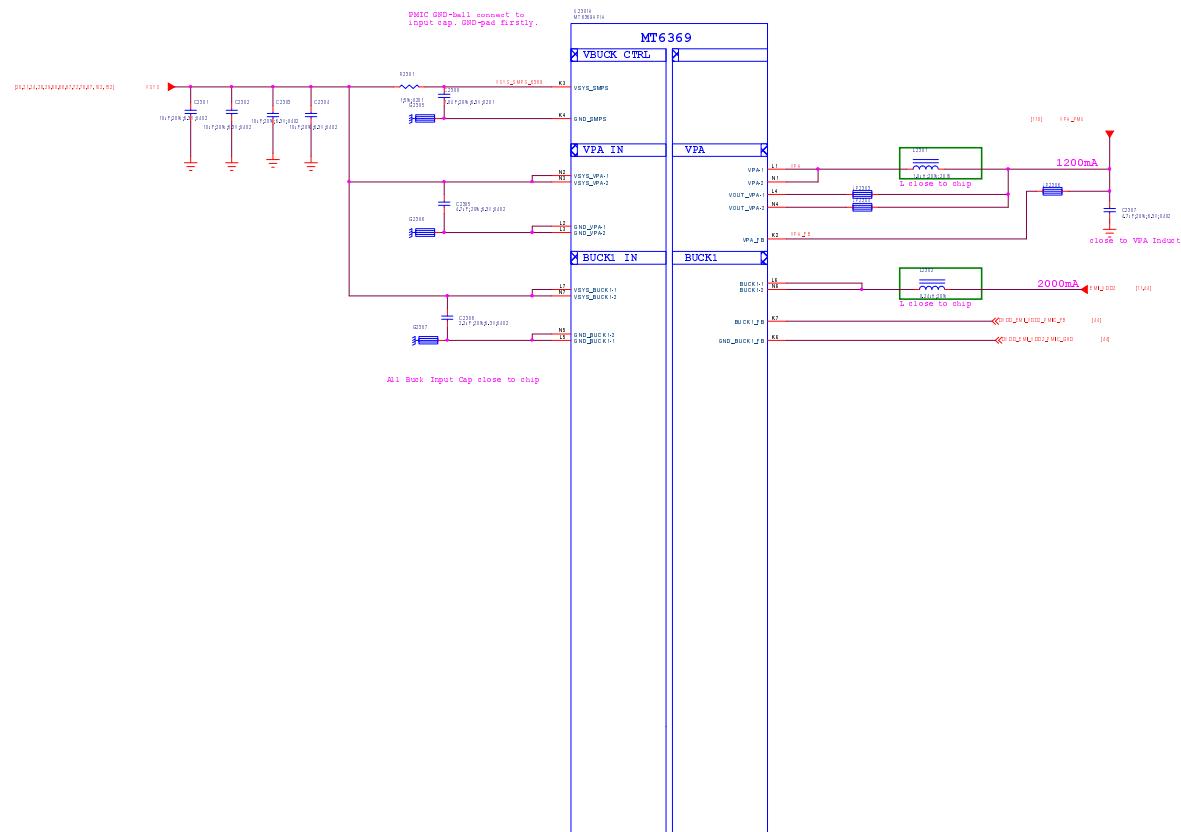
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21_POWER_MT6363-LDO

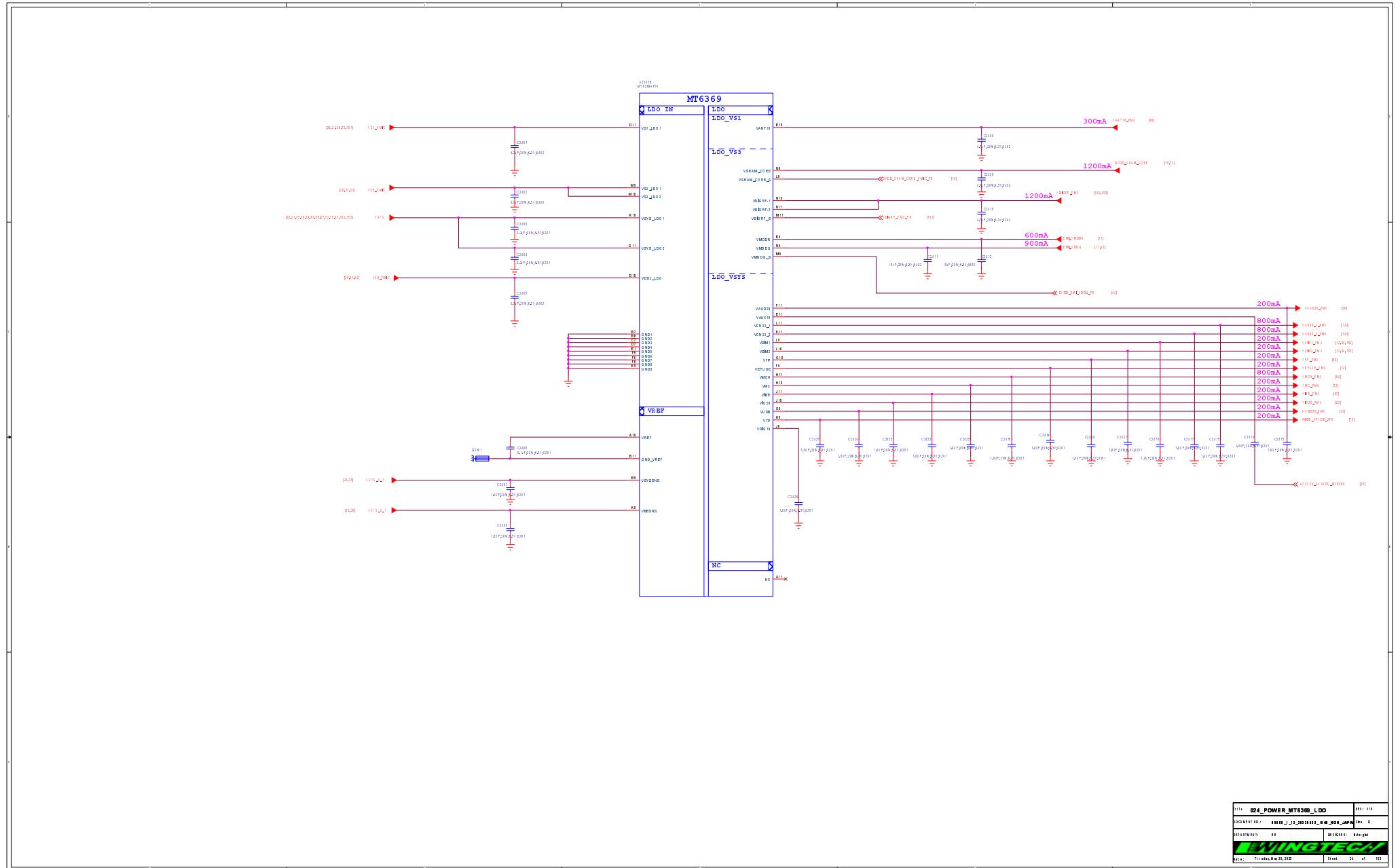


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WINGTECH		

23_POWER_MT6365_Clock

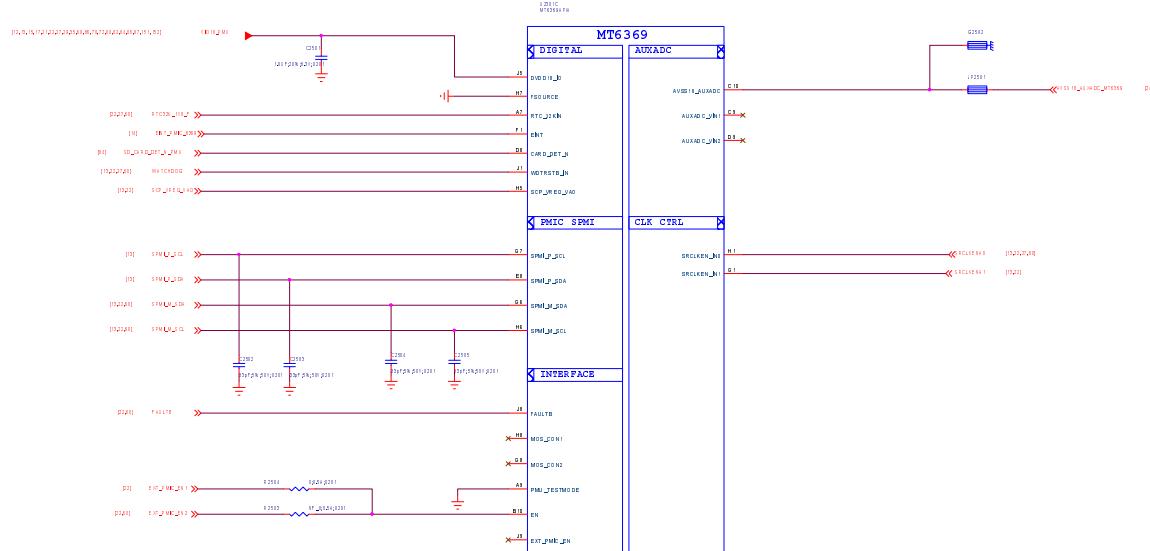


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DATE:	2023-01-10
VER:	1.0
COMPONENTS:	WINGTECH
DATE:	2023-01-10
VER:	1.0
COMPONENTS:	WINGTECH

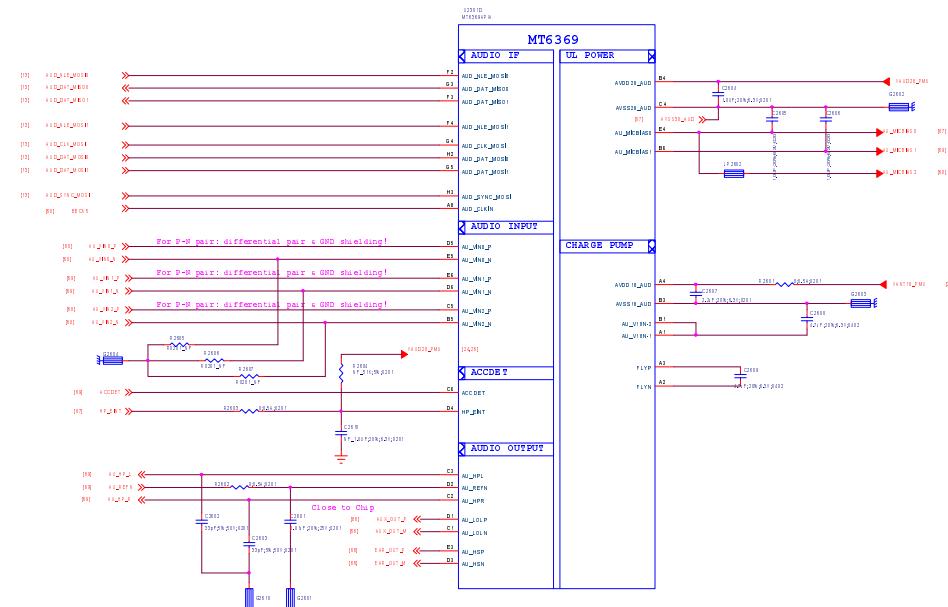


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024_MYSTIC:	01

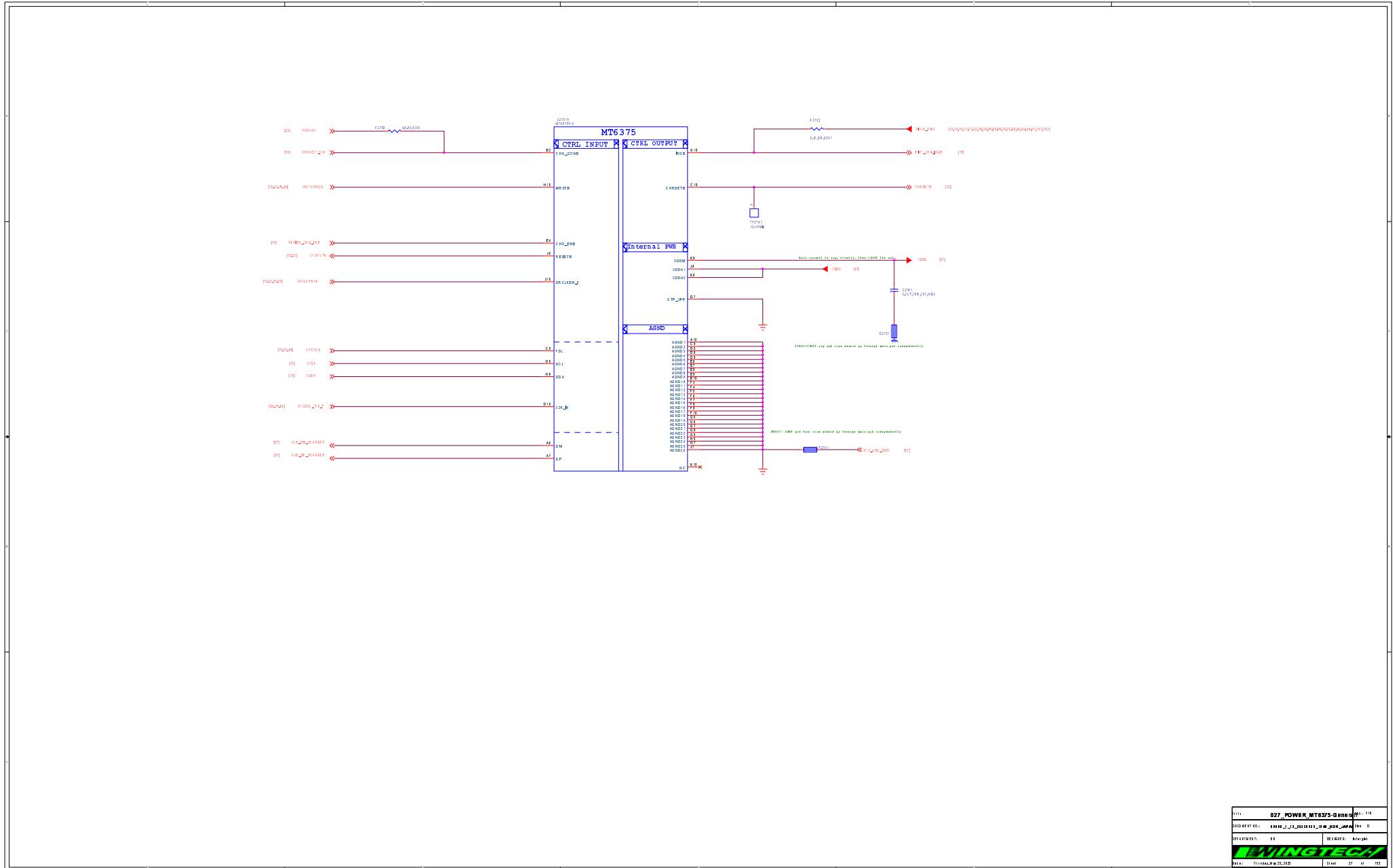
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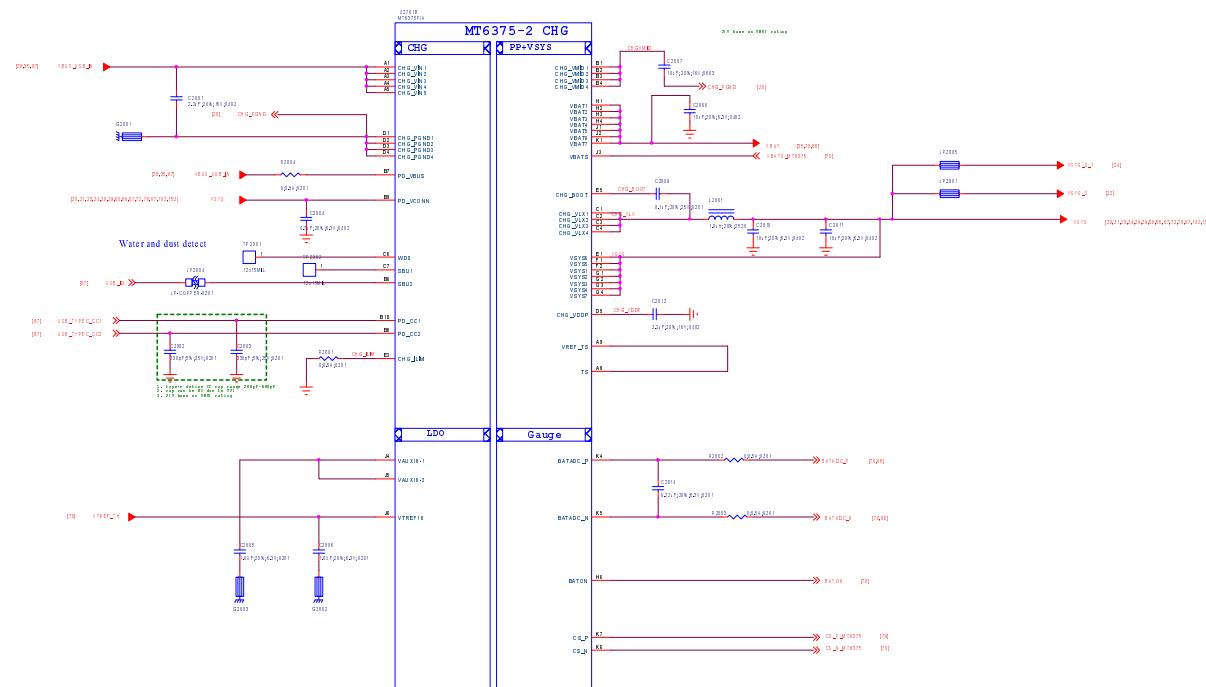


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Revisions: 00	Date: 00/00/00
WINGTECH	
Date: 00/00/00	Page: 20 of 145



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Department:	00	Design:	Design
WINGTECH	WINGTECH	Sheet:	27 of 102

28_POWER_MT6375_Charger

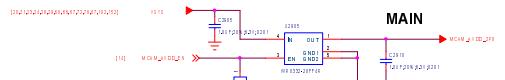


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Page Number:	00 / 00
Date:	2023-01-01
WINGTECH	

CAM_LDOs

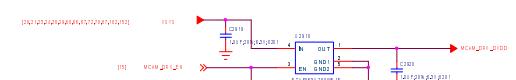
AVDD

CAM_AVDD1_2P8



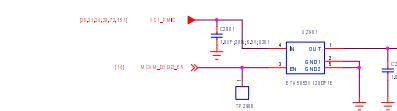
DRV_DVDD

MCAM_DRV_DVDD



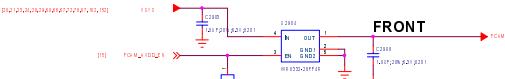
DVDD

MAIN_DVDD :



AFVDD

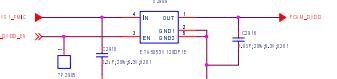
CAM_AVDD2_2P8



MAIN_AFVDD_2P8

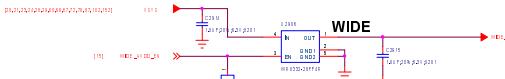


Front_DVDD

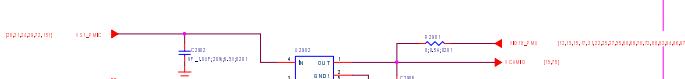


前报DVDD 1.1V, 确认型号后更换

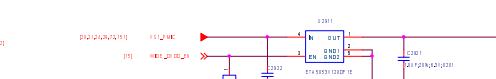
CAM_AVDD3_2P8



VCAMIO



WIDE_DVDD

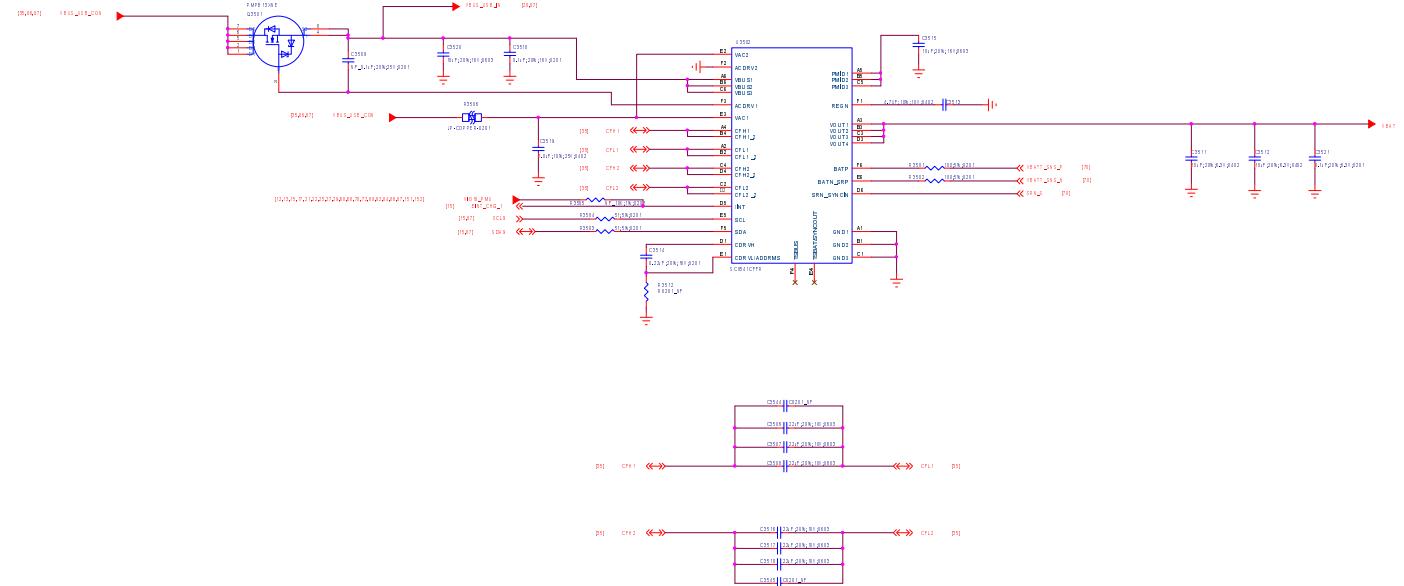


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0281111:	0000_0_0_0_0_0_0_0_0_0_0_0_0_0_0_0_0_0_0
0281112:	0000_0_0_0_0_0_0_0_0_0_0_0_0_0_0_0_0_0_0

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035_Charger

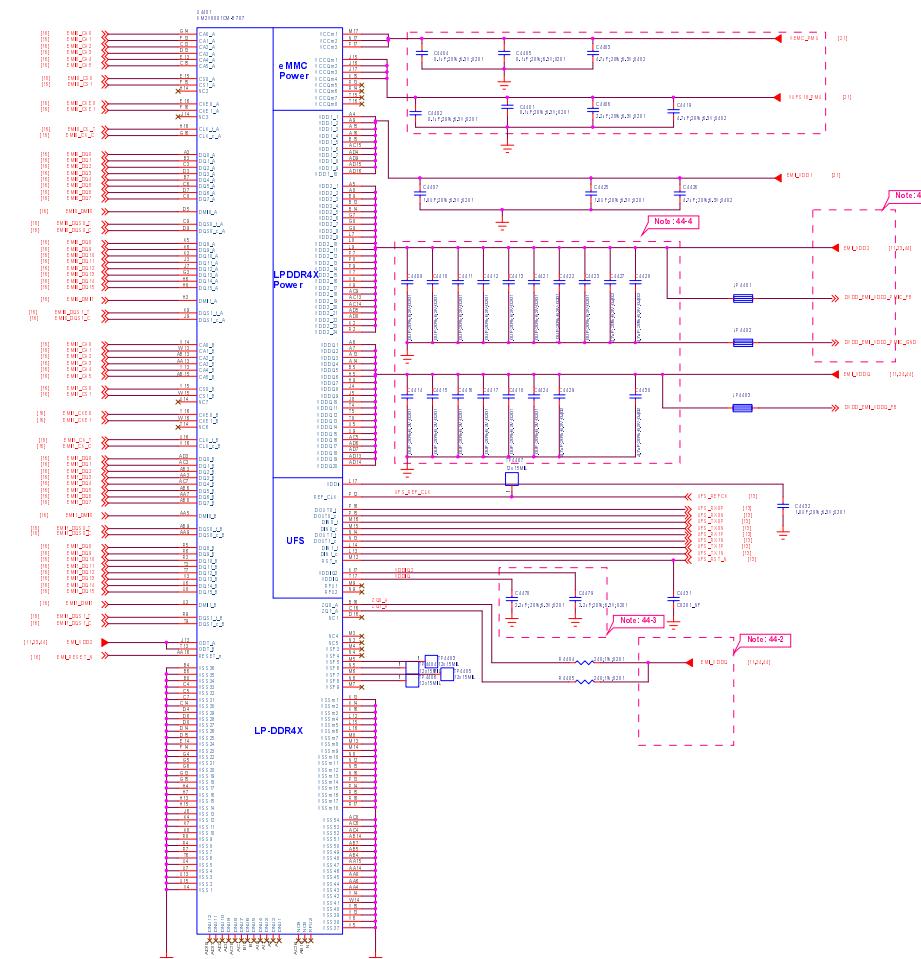
33W



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Manufacture:	00	Printed:	00/00/0000

WINGTECH

44_Memory_UFS_LPDDR4X



Schematic design notice of "44_Memory_UFS_LPDDR4X" page.

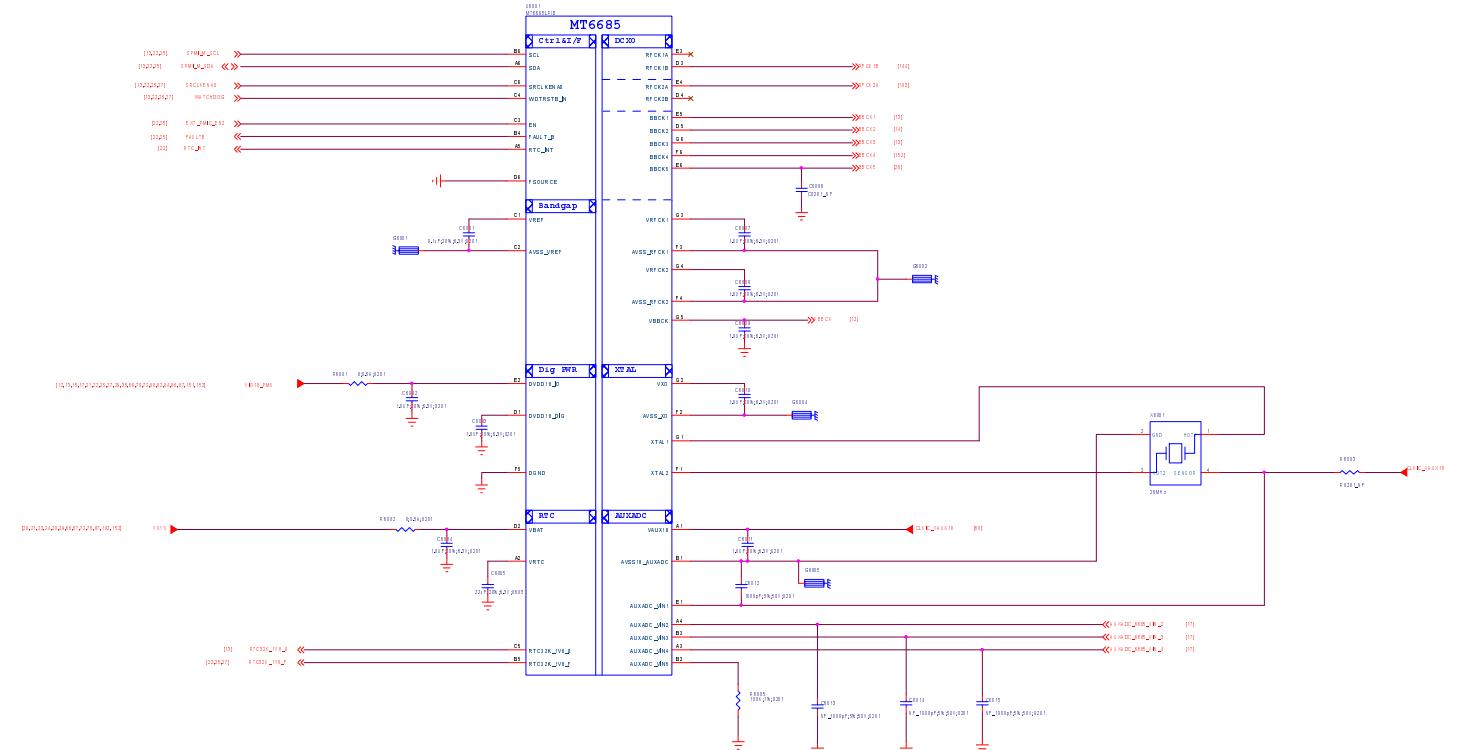
Note 44-1: Please refer to power supply related page select LD07_VOUT / BUCK1_LX output voltage properly for LPDDR4X

Note 44-2: DRAM ZQx resistor = 240 ohm (1%) that must be connected to VDDQ,

Note 44-3: Please refer to uMCP vendor's datasheet or MTK common design notice to get the recommended bypass cap. value for VCCVCCQ/DDI power domains of UFS.

Note 44-4: VDD2_VDD0 decoupling cap. closed to DRAM ball.
For other cap for PMIC (>10uF, at PMIC page);
please also refer to MMD and layout guide for placement

60_MT6685

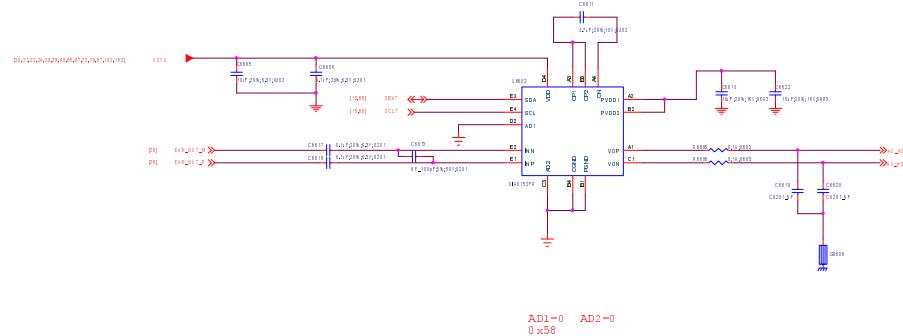
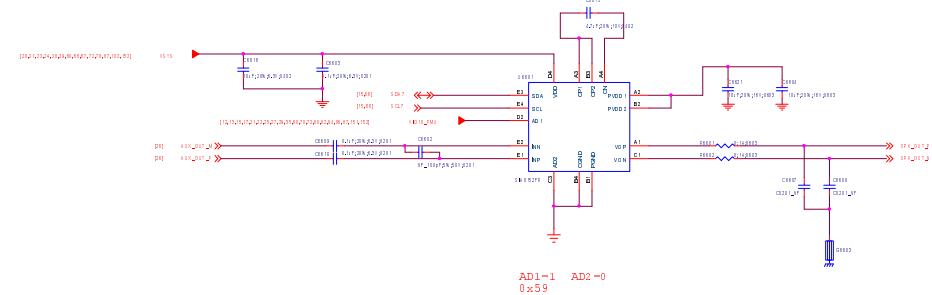


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WINGTECH			

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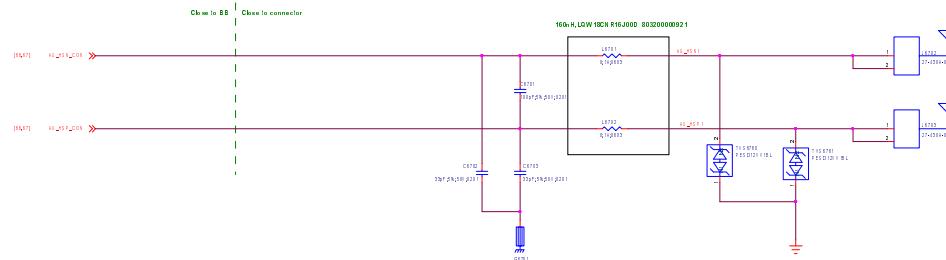
066_SPK

FOR SPK

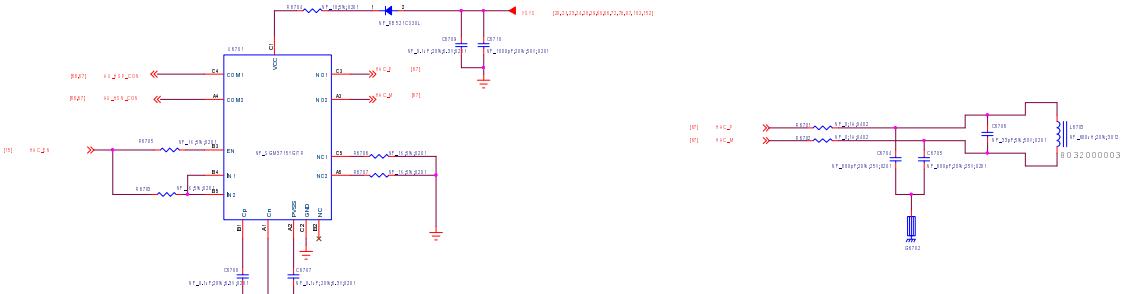


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067_Receiver



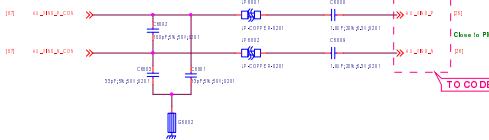
HAC Reserve



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Printed At:	02	Print Date:	00:00:00
WINGTECH	WINGTECH	Date:	07-Nov-2019

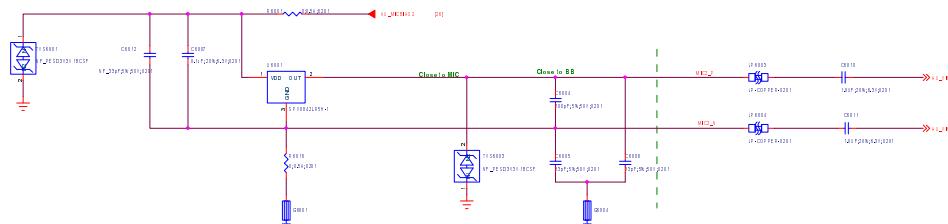
068_MIC

MAIN MIC



AUX MIC

second Microphone

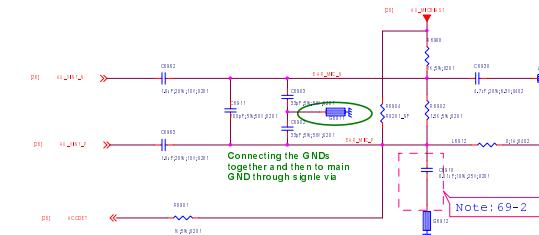
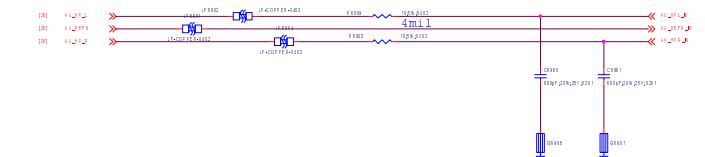


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Document Type:	068_MIC	Version:	0
Comments:	EE	Design:	WingTech
WINGTECH	File: 71068_MIC.dwg	Sheet: 10 of 10	

069_Earphone

Earphone Microphone

TO CODEC



Schematic design notice of "62_PERI_AUDIO_IO" page.

Note 69-1: Part # of BEAD6202, BEAD6203, BEAD6204 and BEAD6205 needs changed to "BLM18BD102SN1" for high THD performance |-90dB| but this BOM change will results in FM RSSI 10dB degraded .

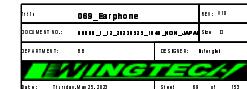
Note 69-2: Reserved Cap C6910 for CS/RS test, please double check multi-key function when used

	Earphone_Sink	Earphone_Sink
Earphone_Sink	-	-
Earphone_Sink	-	-

Note 4-4: 1. Need do SW configuration for DCC mode
2. Analog input HI Impedance is as below, please customer check the detail requirement with mic vendor if the mic has specific requirement on the input impedance of analog input

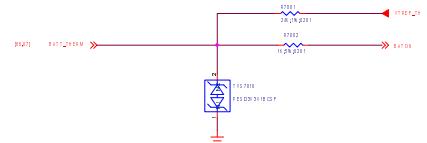
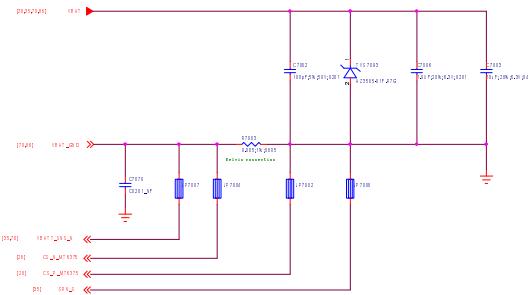
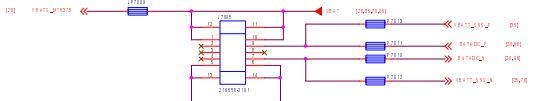
Min(V)	Max(V)	Min(I)	Max(I)	Unit
0	2.0V	-	1.0	V

Note 4-5: Please select R6231 with 0402 size



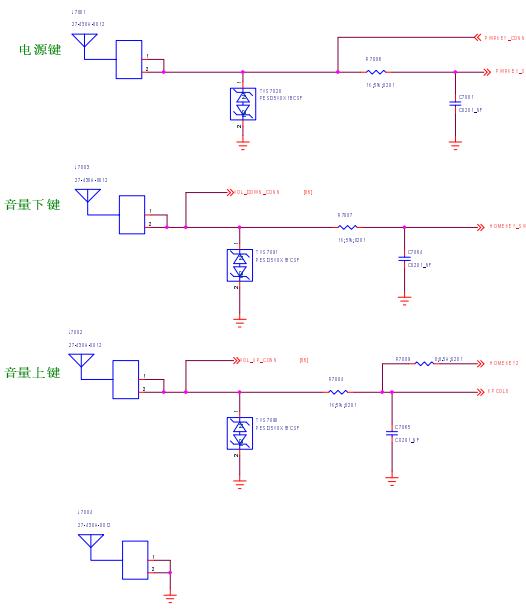
070_Battery/Sidekey

BATTERY CONN



Power Key / Key Pad

DO NOT put pull-up resistor on PWRKEY



RAMDUMP debug key

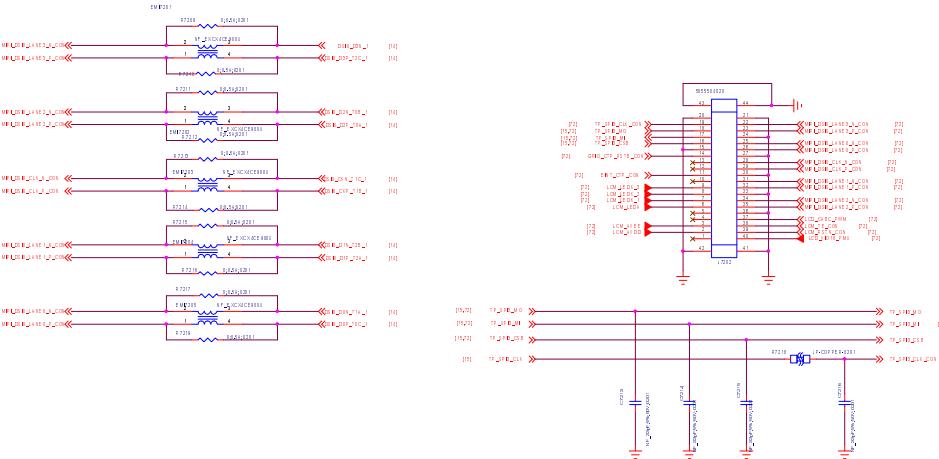
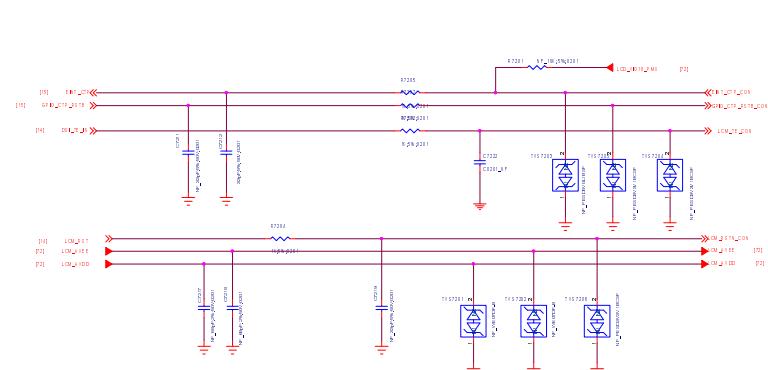


070_Battery/Sidekey		Rev: 00
Document ID:	0000_0_0_00000000_0000000000000000	Date: 00/00/0000
Department:	00	Design: Design
WINGTECH		Page: 73 of 103

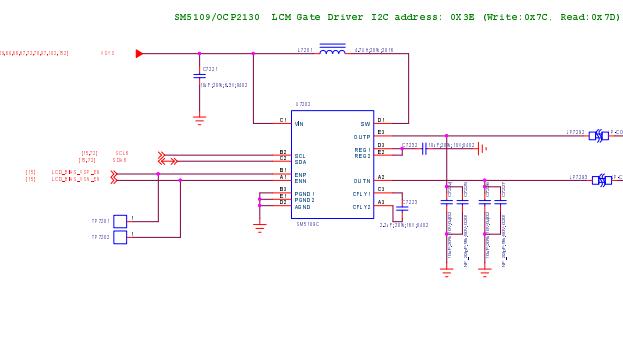
072_LCD/CTP IF

MIPI CMF

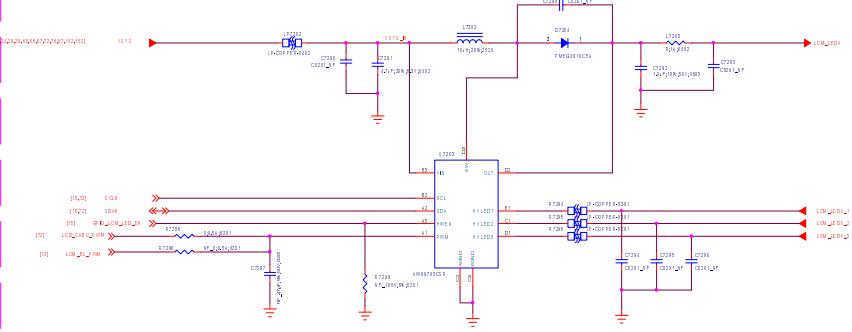
CMF
1st:811310000121
2st:811310000126



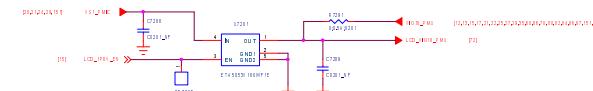
LCM Gate Drive



LCD-BACKLIGHT



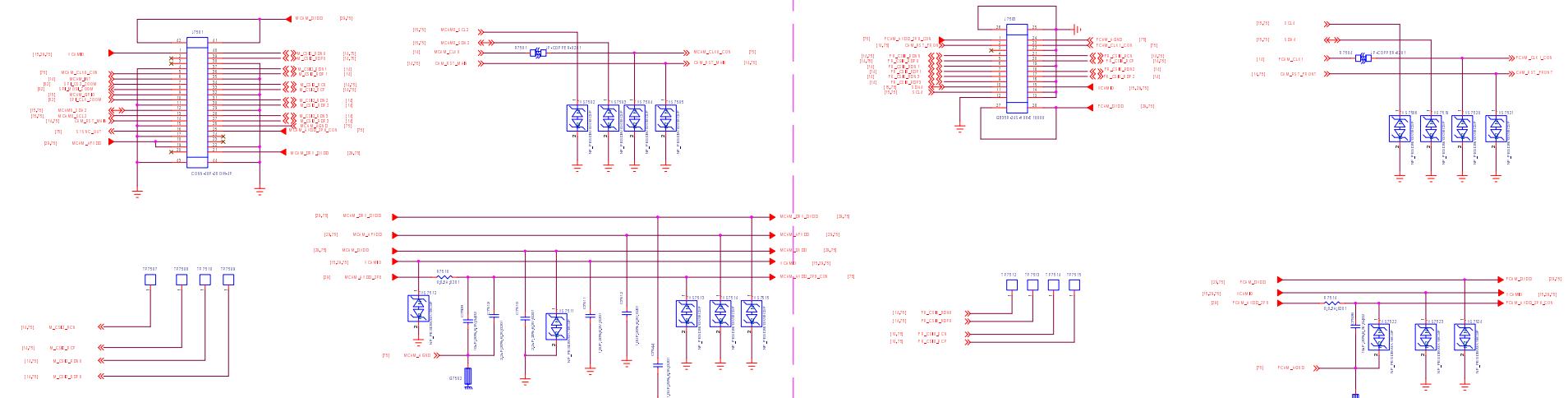
Reserve for ESD



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Document ID:	00001100000000000000000000000000	Version:	0
Printed:	2024-01-16 10:00:00	Page No.:	1
WINGTECH	www.wingtech.com	Email: 72	ID: 002

41 CAMERA IF

Main Camera 50M



2MP Macro
8MP Wide compatible

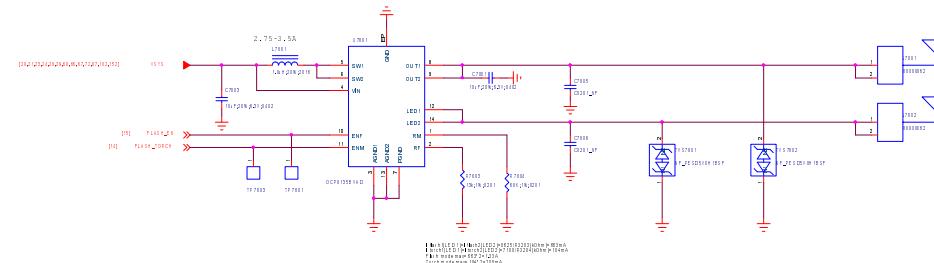
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WINGTECH

078_Flash/RGB/Vibrator

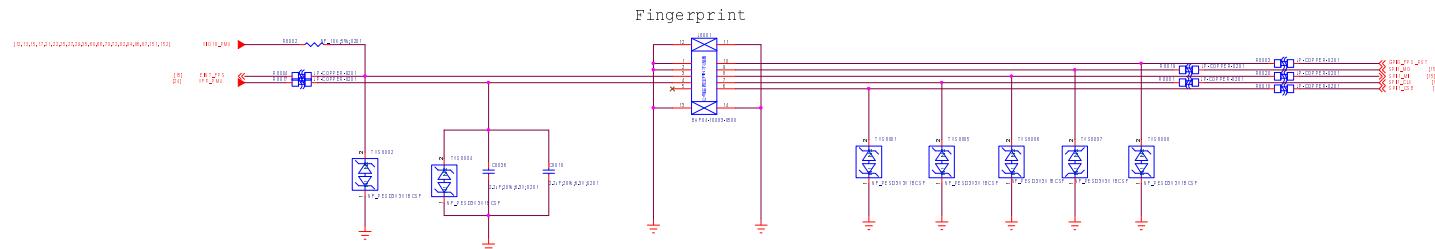
Flash LED

Flash Driver



Title:	078_Flash/RGB/Vibrator	Date:	11/11
Document No.:	0000_00000000000000000000000000000000	Design:	0
Department:	00	Design:	0000
WINGTECH	00000000000000000000000000000000	Page:	73 of 103

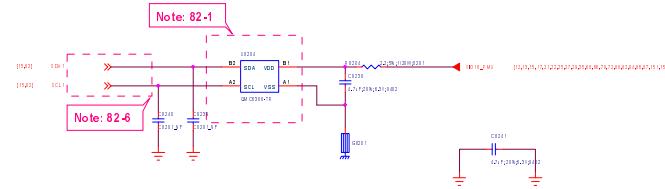
080_FingerPrint



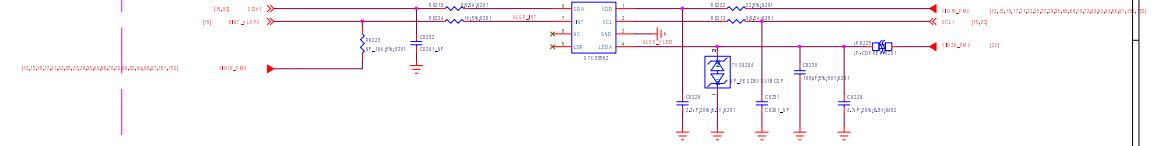
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WINGTECH	00	Design:	0000

082_SENSORS

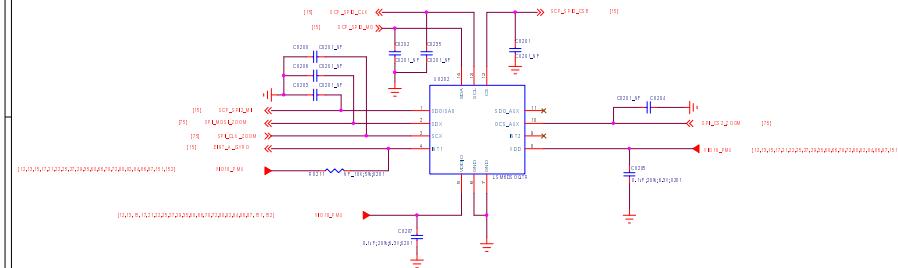
M-SENSOR



ALS+PS+IR

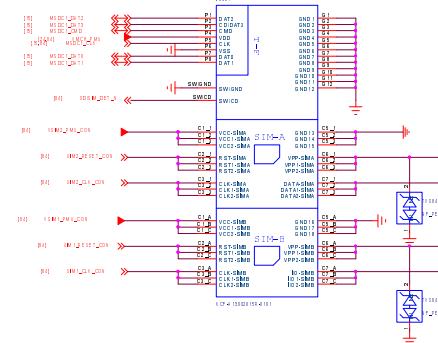


Gyro Sensor

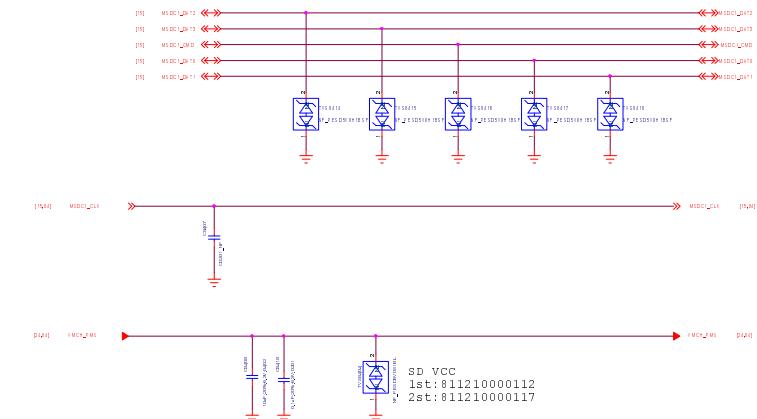


084_SIM/SD IF

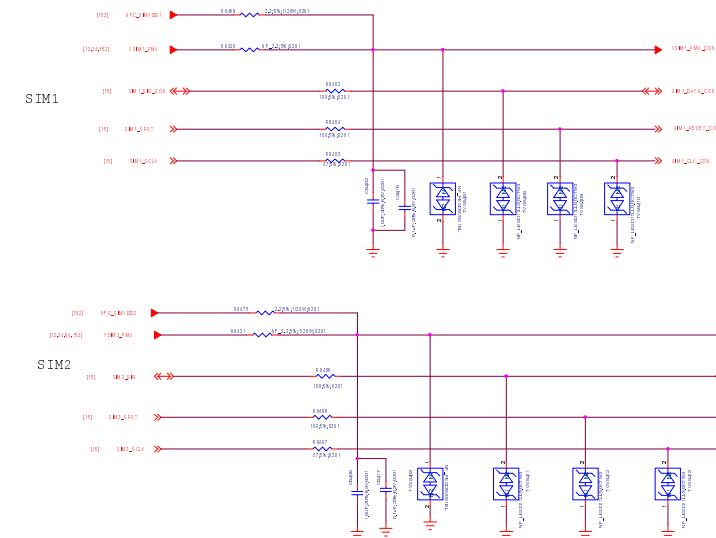
SIM & T_Card Slot



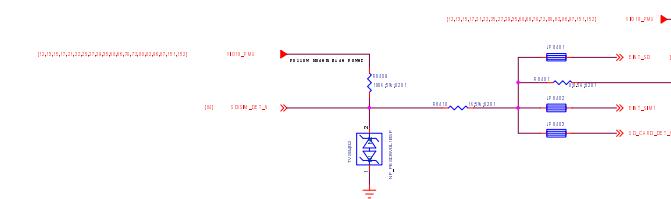
T_Card



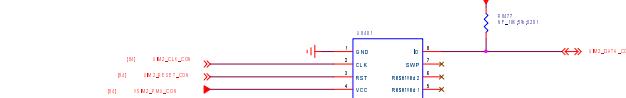
SIM CARD



Detect



eSIM Reserve

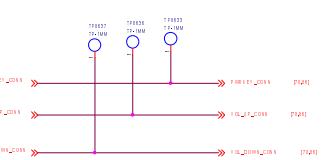


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Comments:	00	Design:	WingTech
Created:	0000-00-00 00:00:00	Last Update:	0000-00-00 00:00:00

WINGTECH

086_Testpoint/Shielding/GND

SIDEKEY

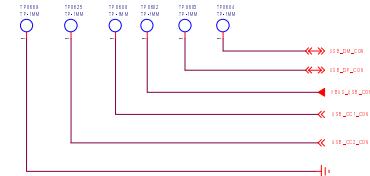


FORCE DOWNLOAD

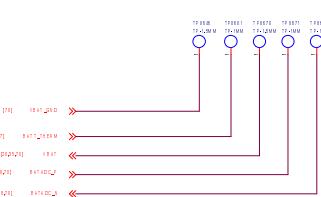
FORCE BOOT



USB



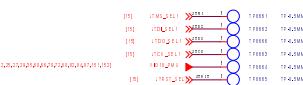
Battery



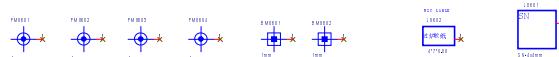
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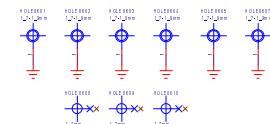
JTAG



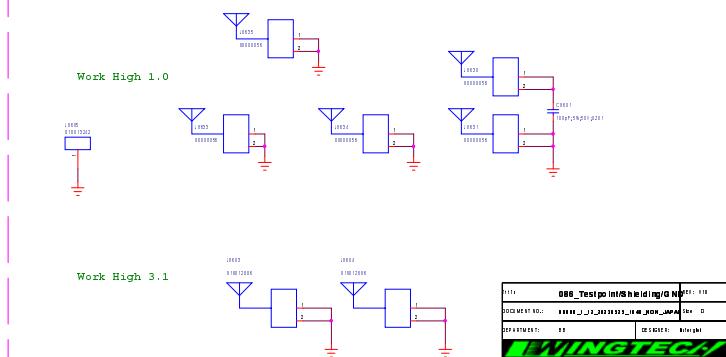
MARK/Shield/Label/PCB



Hole



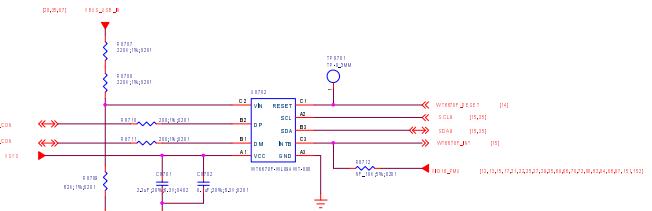
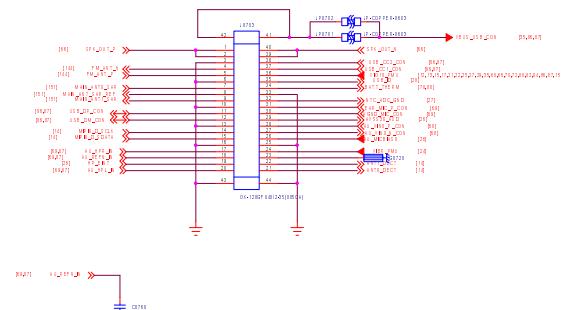
Spring GND



087_Sub PCB IF / USB IF

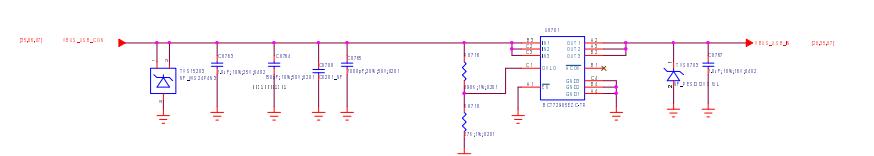
QC3+

预留0603占位封装，解RF desence问题



OVP

OVP 11.2V



$$V_{OVP} = 1.2 * (1 + R8716 / R8718)$$

$\rightarrow V_{OVP} = 11.2V$

when $R1401 = 390K$ // $R1404 = 47K$

087_Sub PCB IF / USB IF	
Document ID:	087_JJ_0000001_HW_DOK_WW
Department:	EE
Designator:	WINGTECH

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101.RF_Block

REVISIONS			
REV	DESCRIPTION	DATE	APPROVED
A	INITIAL RELEASE		

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C

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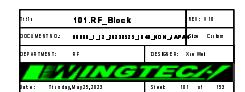
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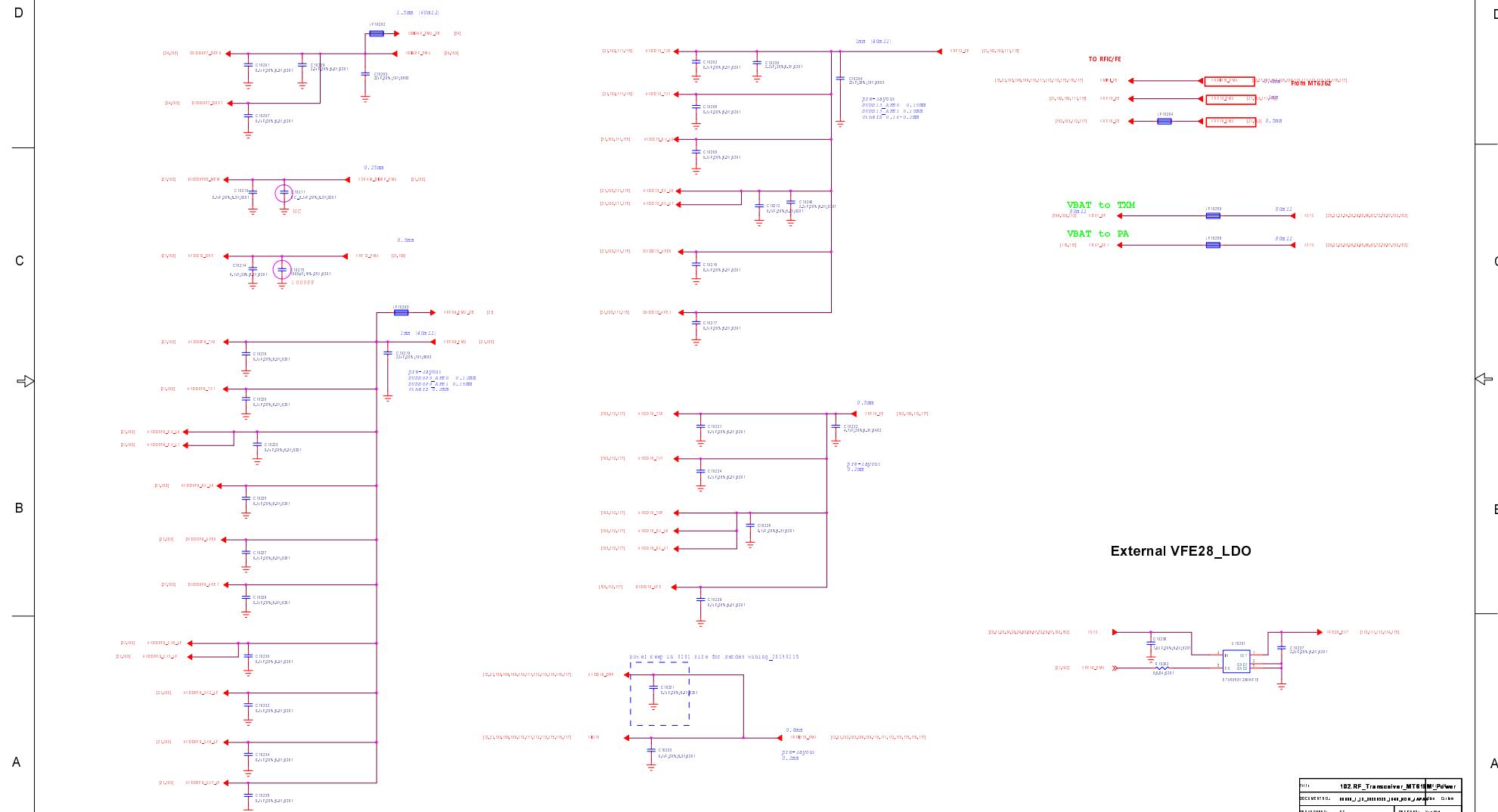


8 7 6 5 4 3 2 1

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A	INITIAL RELEASE		

102.RF_Transceiver_MT6190M_Power

Power Supply of Transceiver



Rev 102.RF_Transceiver_MT6190M_Power	
Document ID:	102.RF_Transceiver_MT6190M_Power
Revised:	01
Date:	2023-07-10

WINGTECH

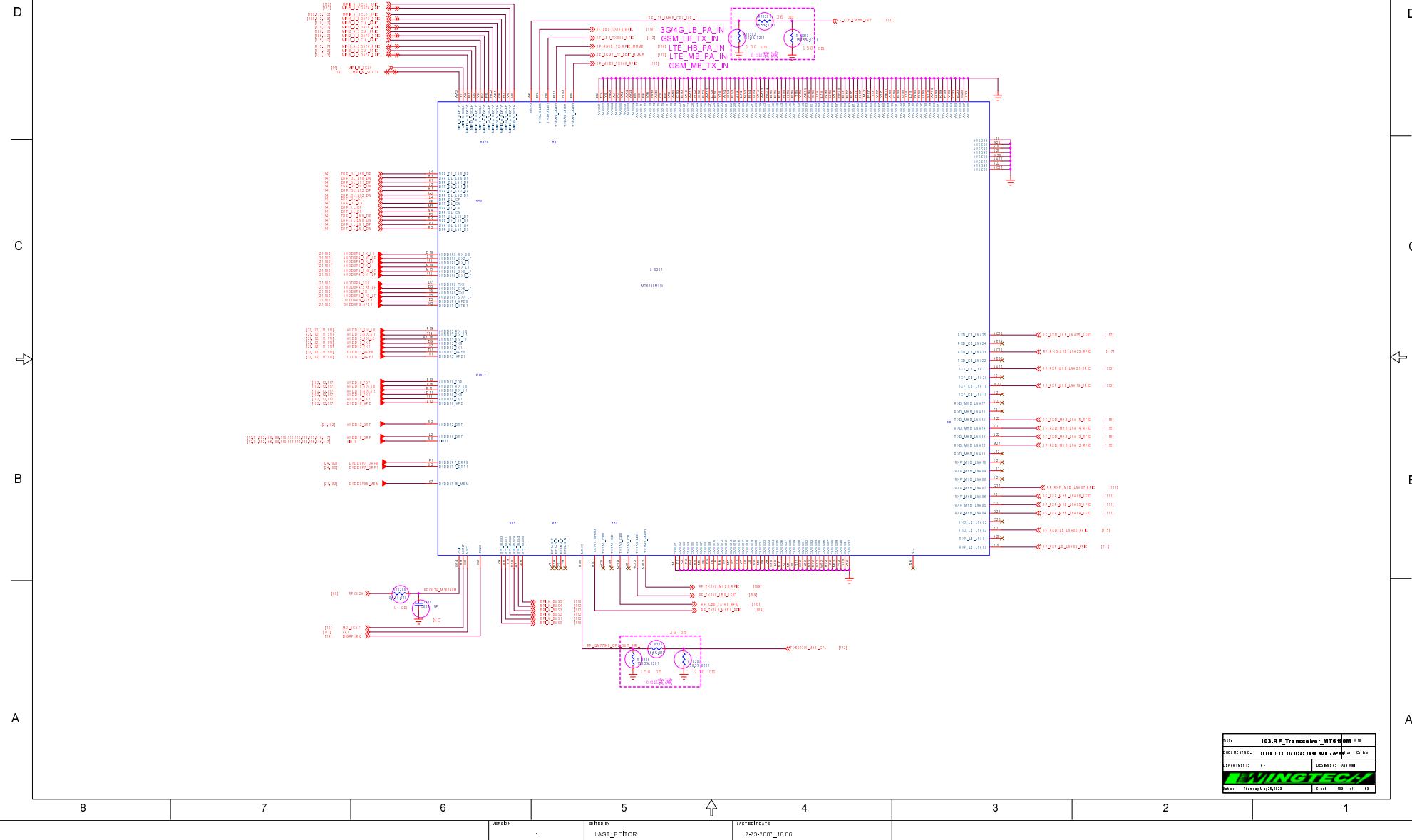
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VERSION 1 REPO BY LAST_EDITOR LAST EDIT DATE 2023-07-10 10:06

103.RF_Transceiver_MT6190M

Transceiver MT6190M

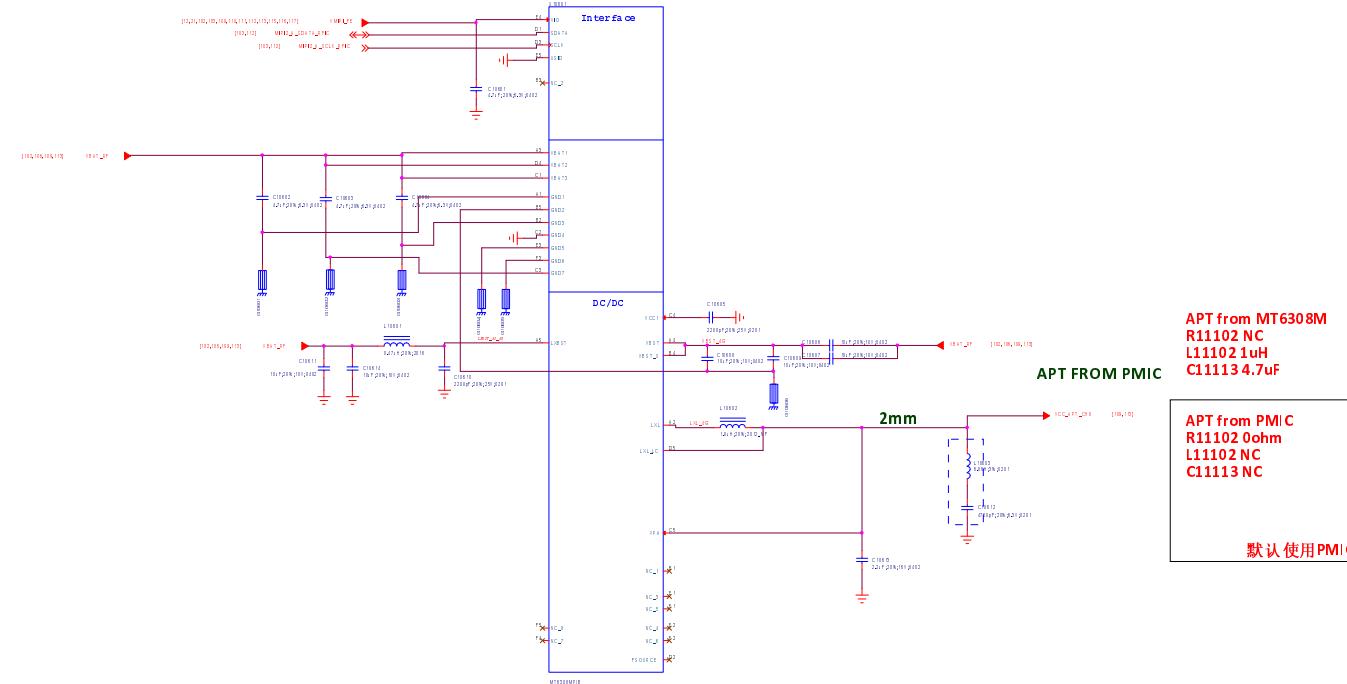
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A		INITIAL RELEASE		



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DOCUMENT ID:	00000_1_1_11111111111111111111111111111111	Page:	0
STAFF MEMBER:	EF	DEPARTMENT:	Hardware
 WINGTECH			Date: 11/06/2018 10:25:2020 Street: 100 st 100

111.APT/ET_Module_1

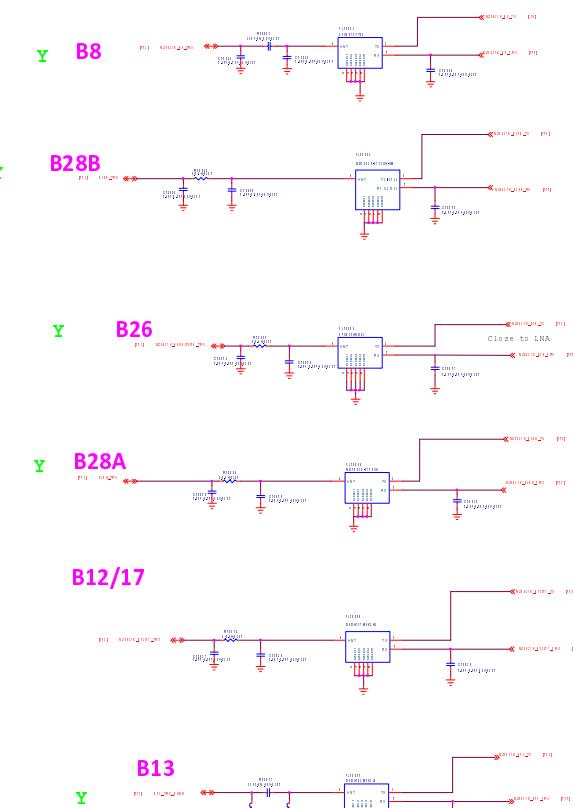
APT for NZ5627K/SKY58081 TX0



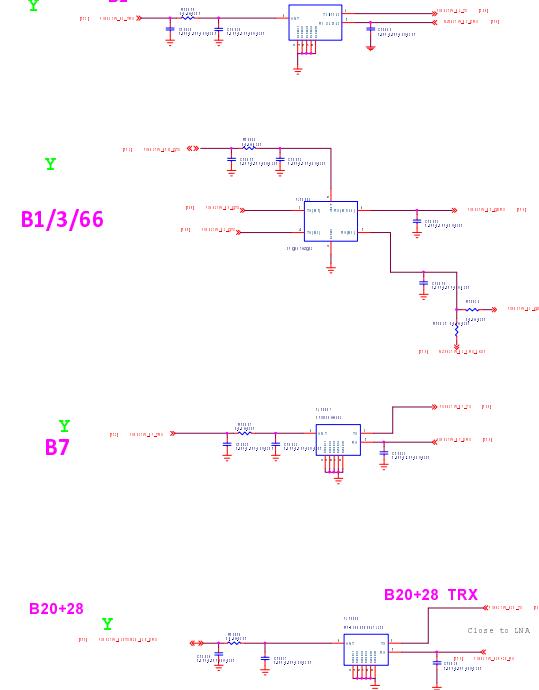
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Author:	WINGTECH	Date:	2023-01-10
Page:	108	Sheet:	1 / 18

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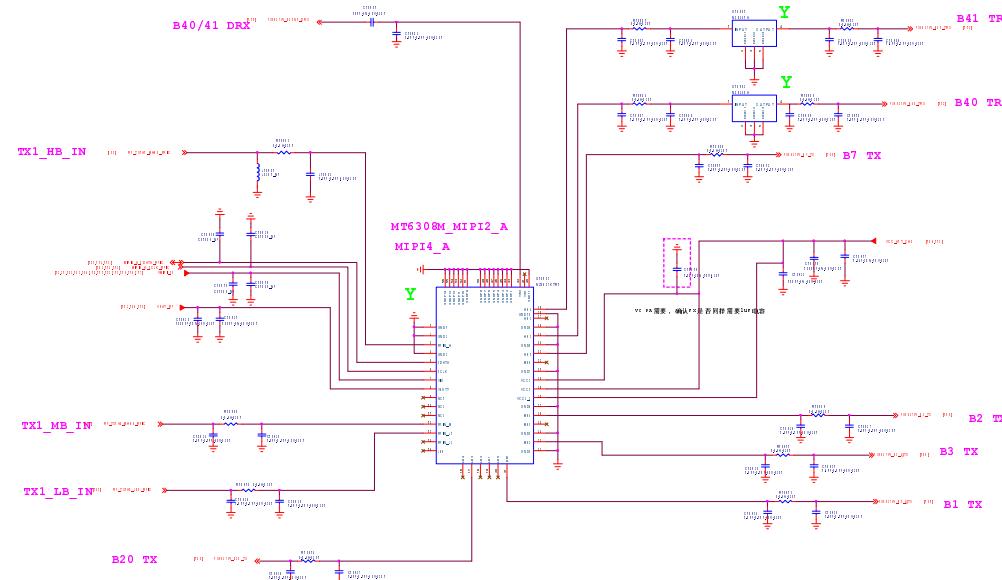
下PA NZ5627K_L



上PA NZ5627K_LMH

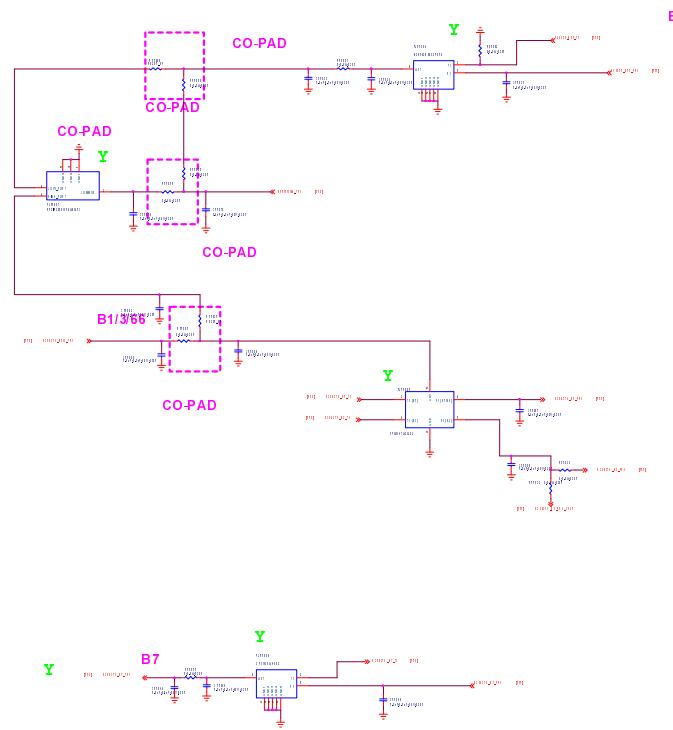
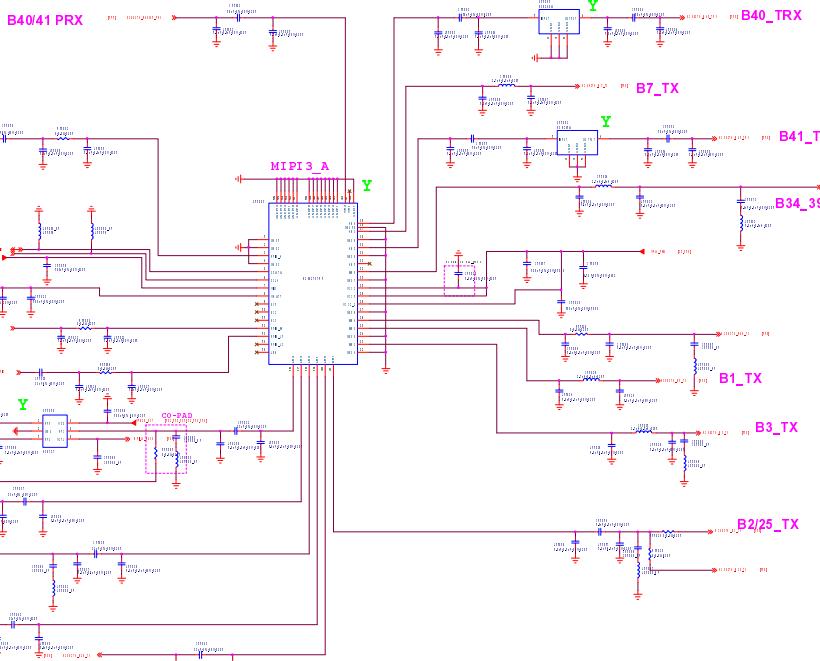


109.NZ5627K 上PA

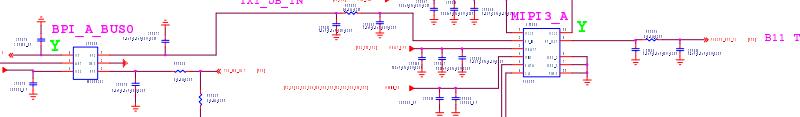


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001	00000000000000000001
010	00000000000000000010
011	00000000000000000011

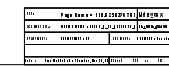
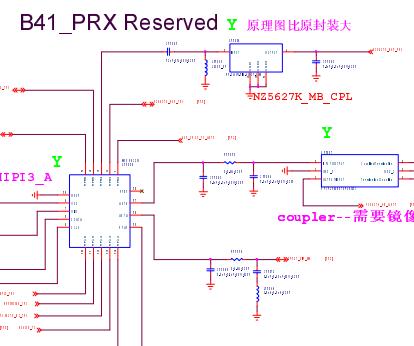
110.NZ5627KTR1-下PA+ FX5311_B11_PA

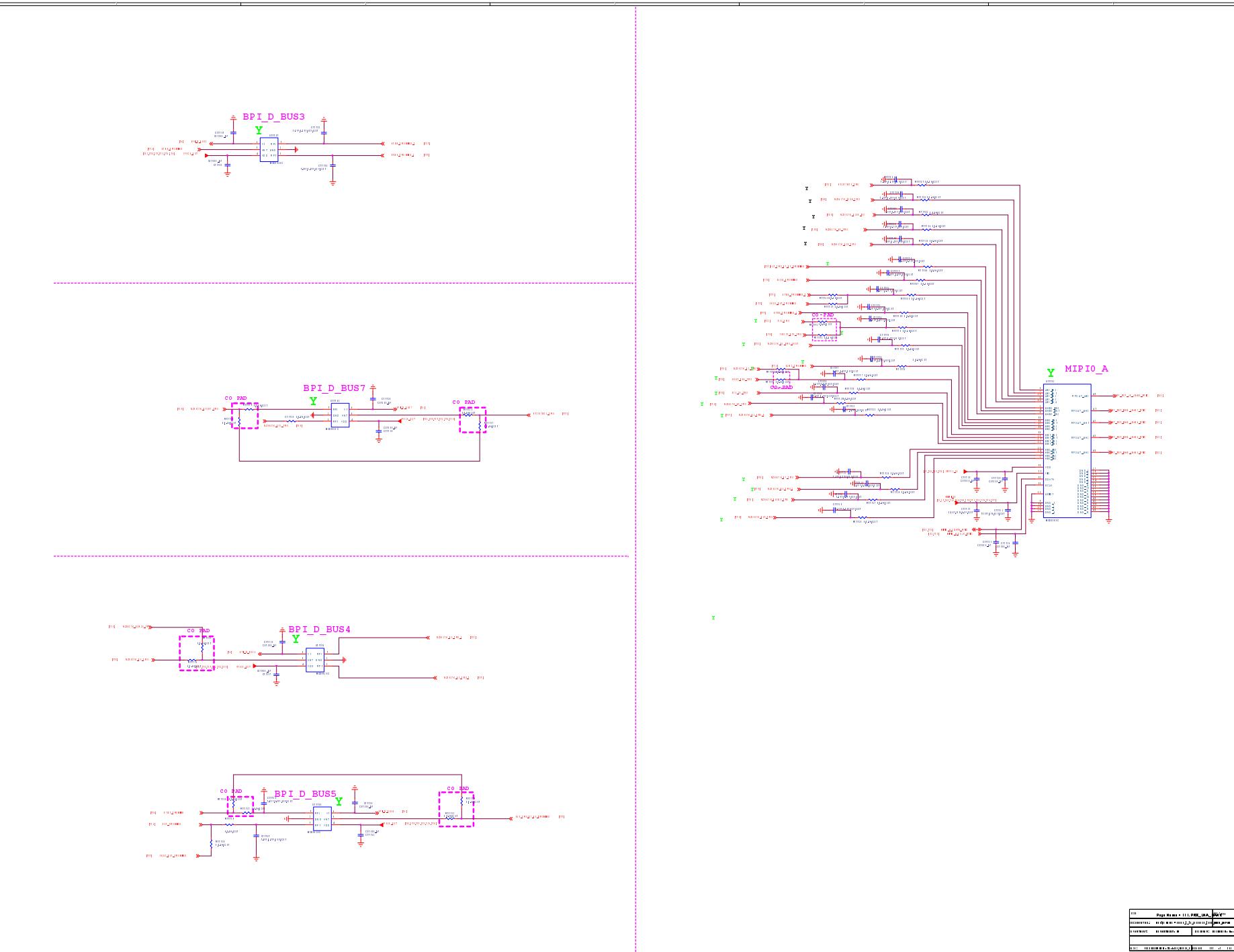


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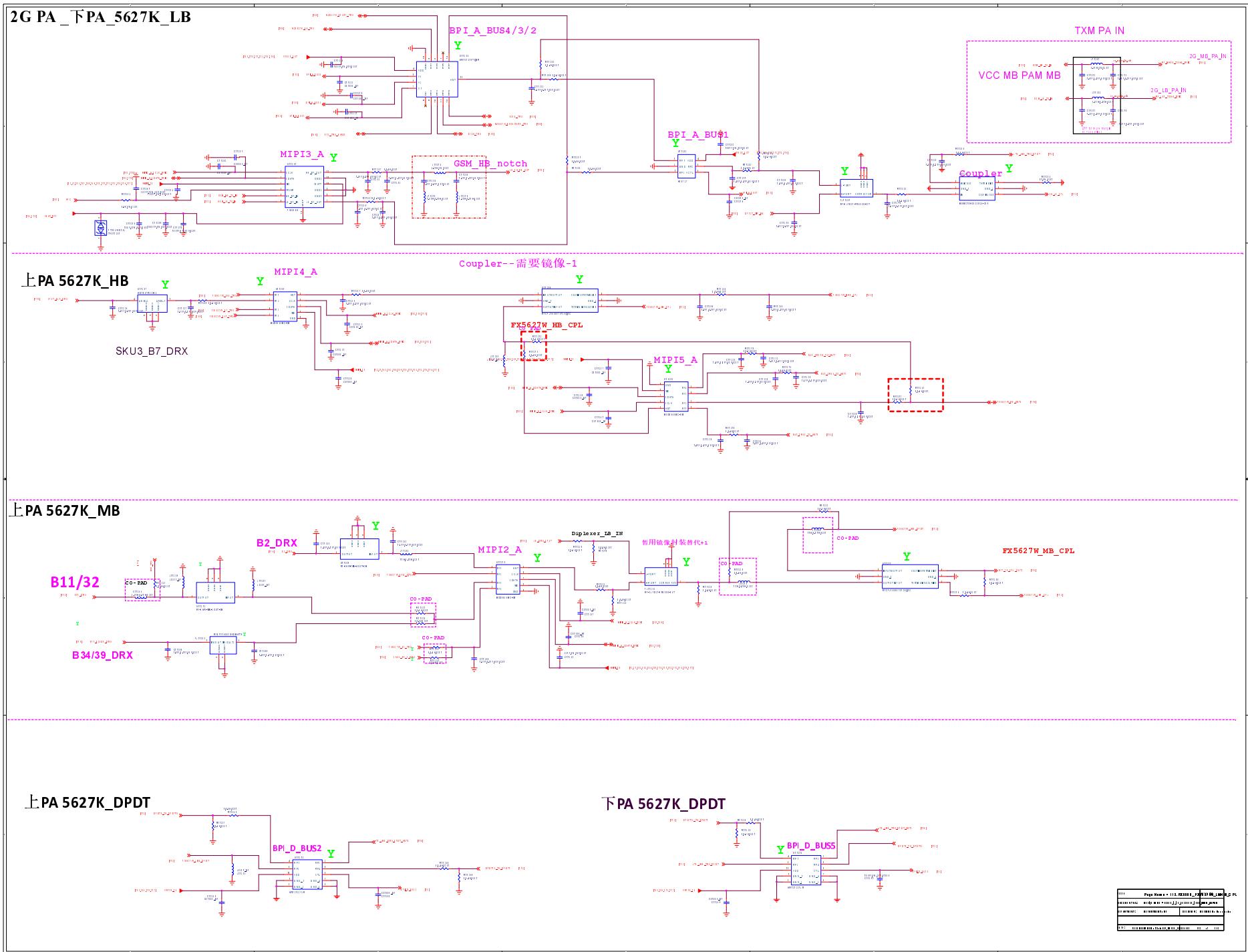


DP12T





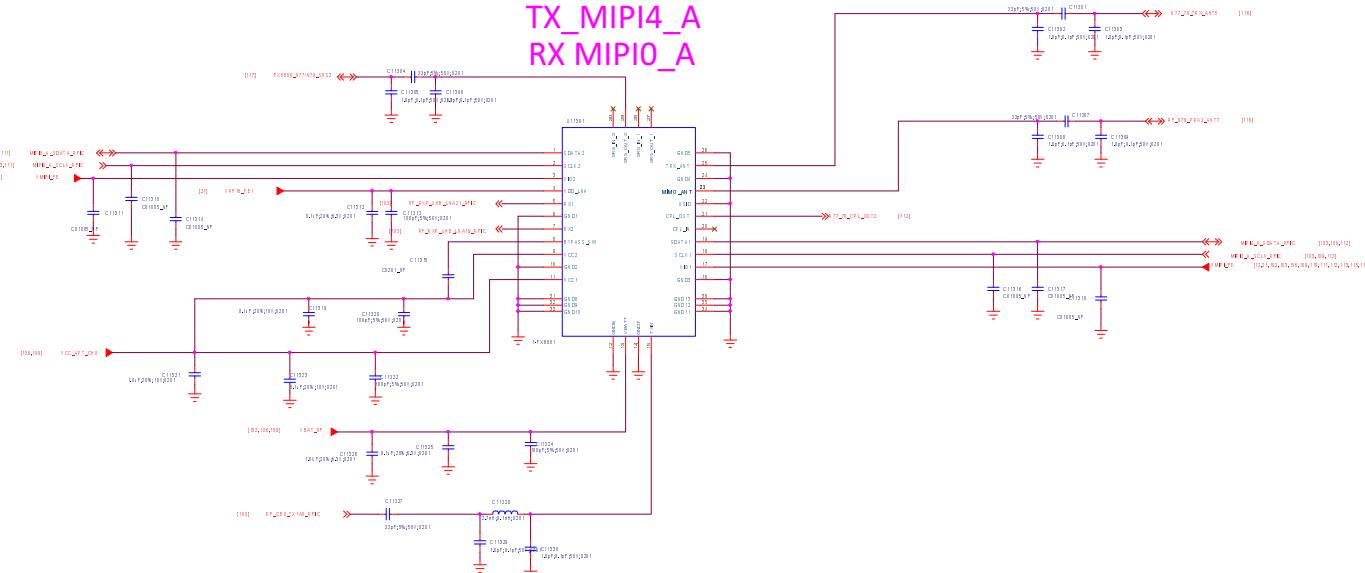
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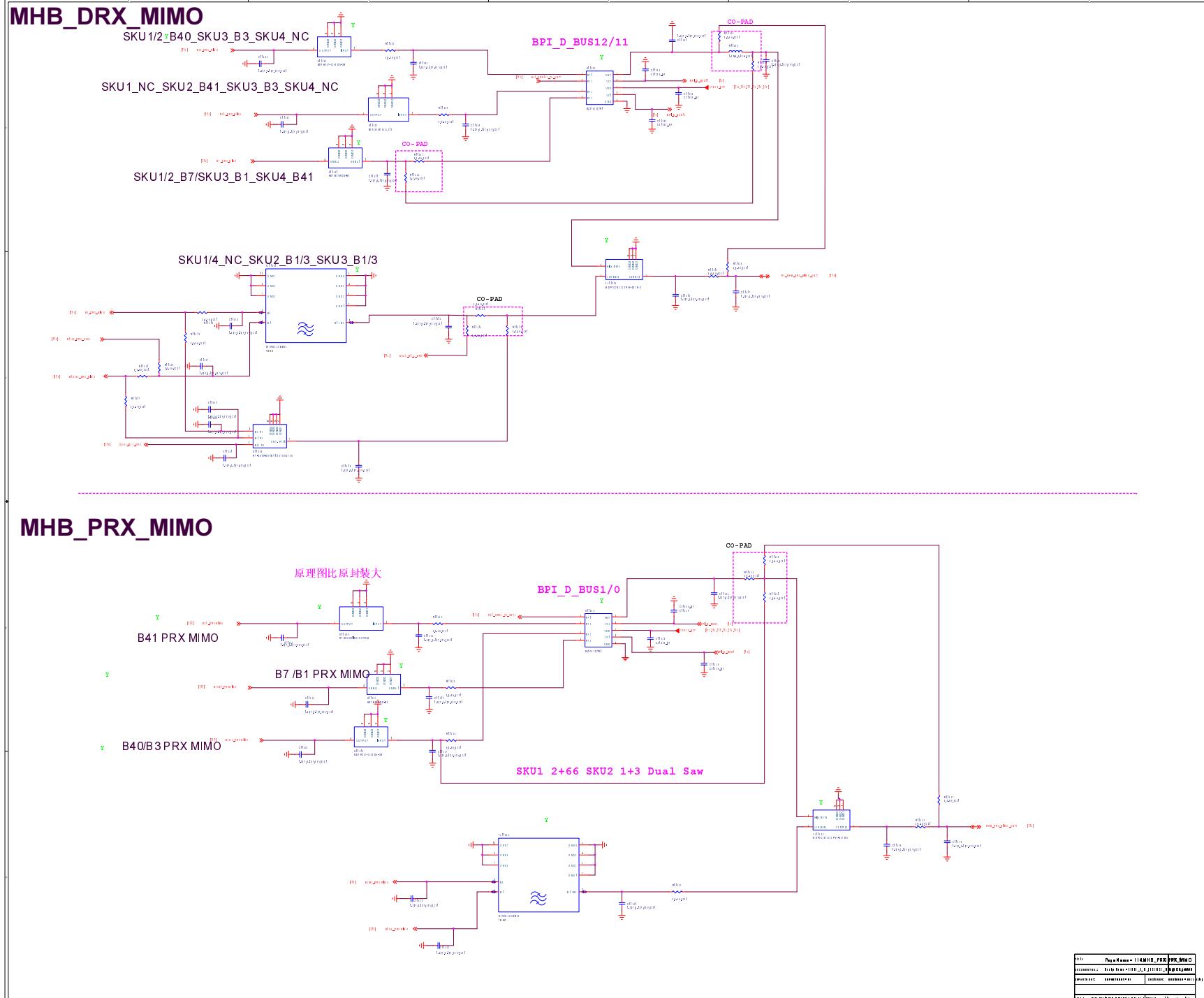
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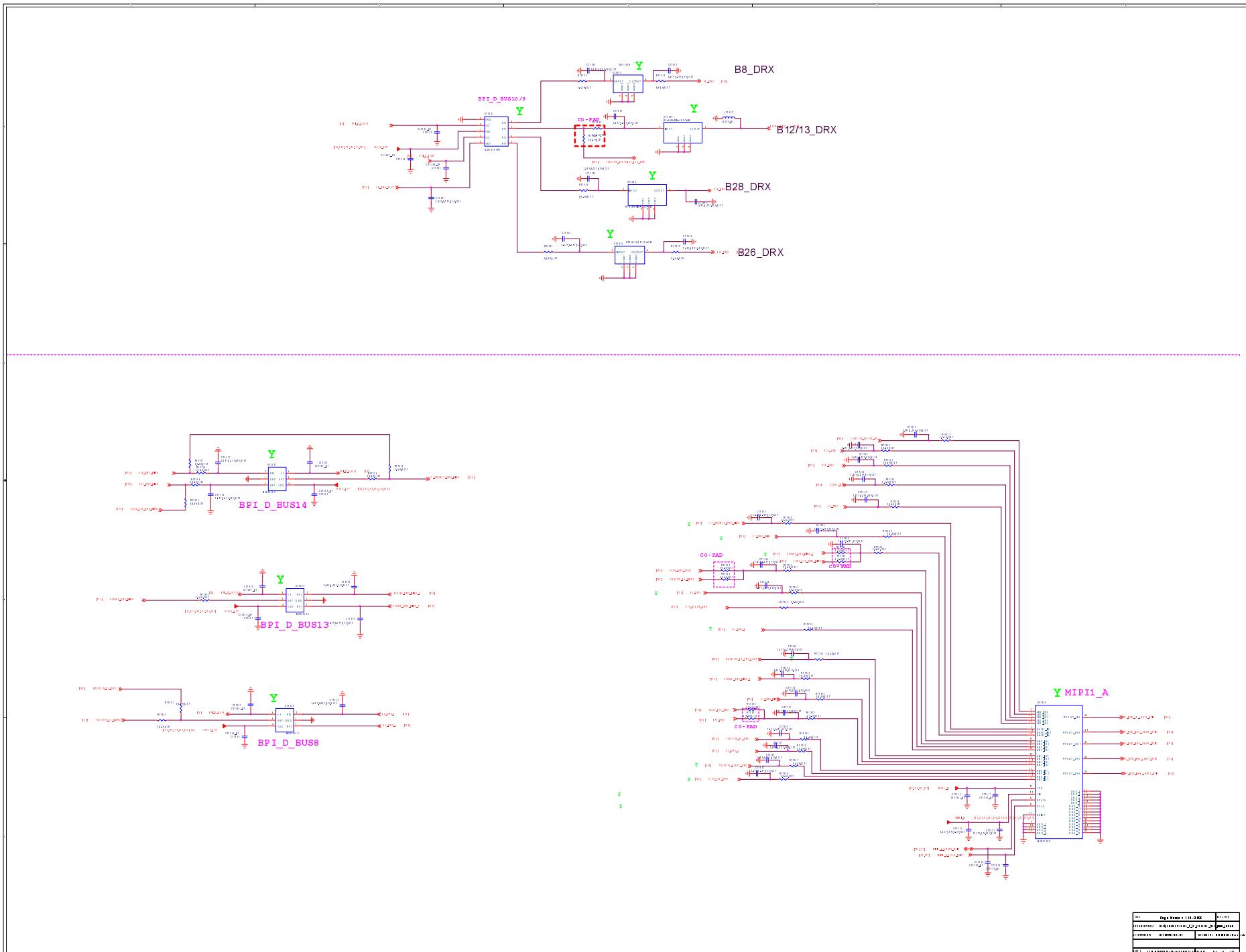
N78 SRS&TRX
MT6308M_MIPI2_A

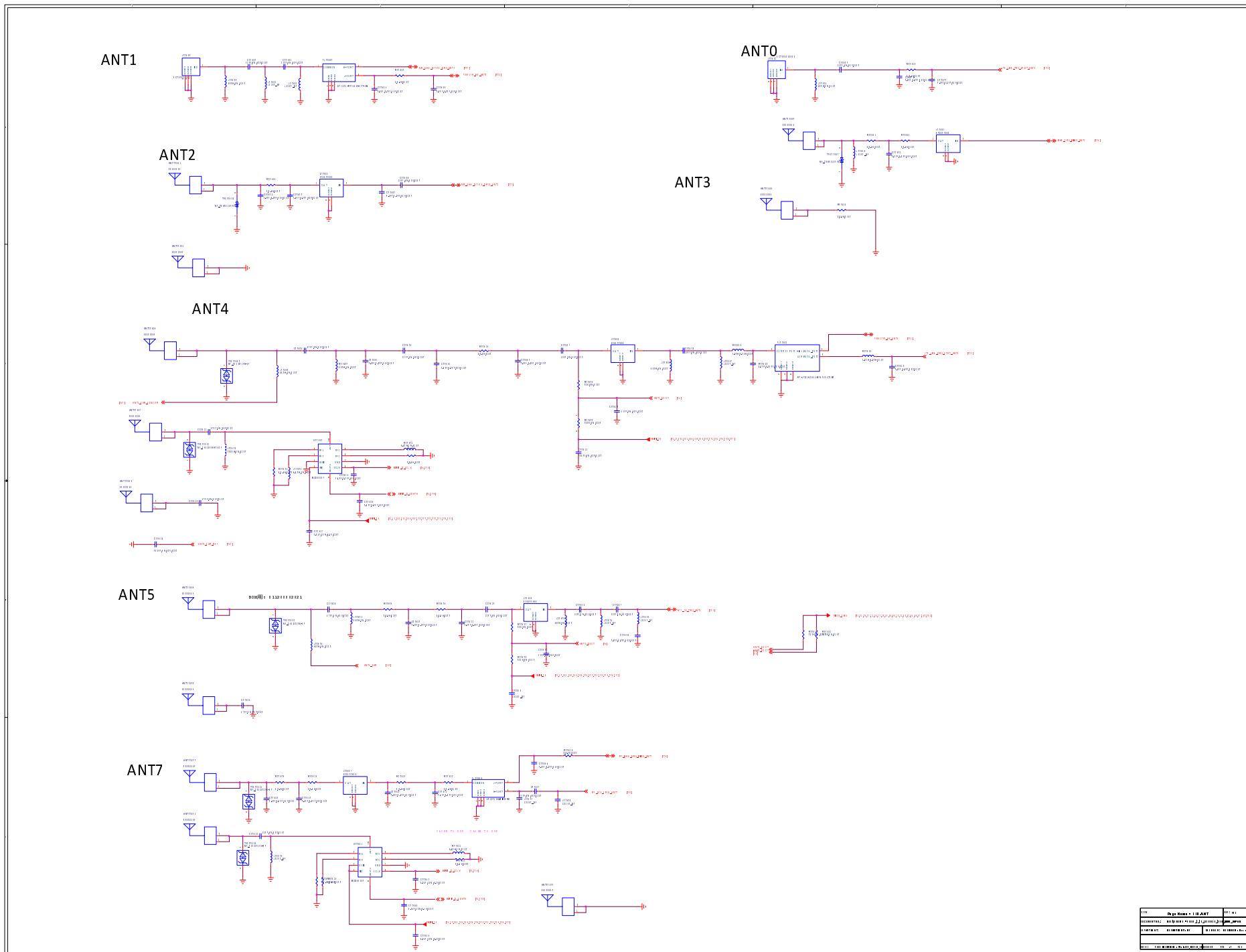
TX_MIPI4_A
RX_MIPI0_A



Page Name = 113_N77_78 TRX	Page No.: 113
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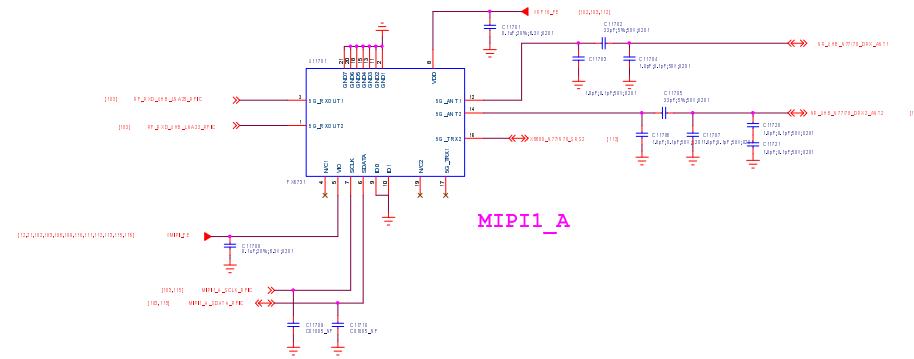






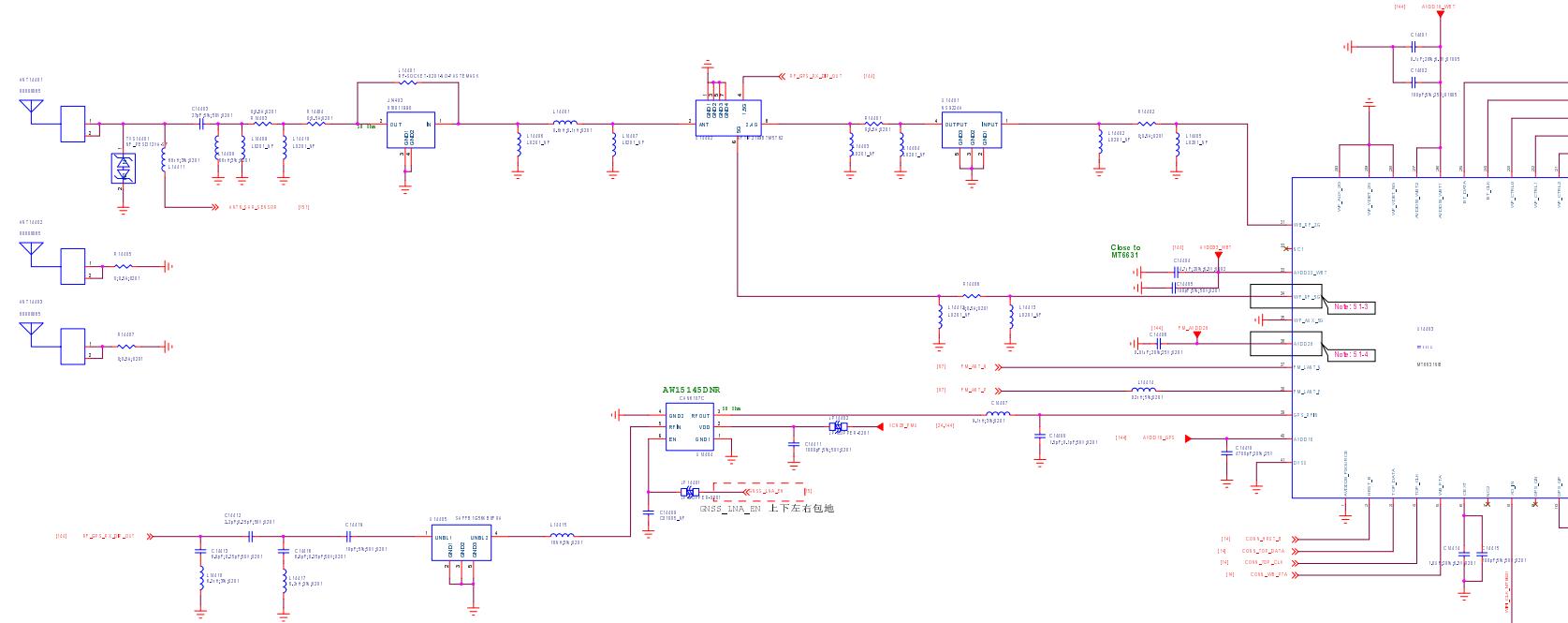
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100	100
100	100

117.N77\79_DRX_DRX-MIMO



8	7	6	5	↓	4	3	2	1									
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version	REPO BY	LAST EDIT DATE															
1	LAST_EDITOR	2-23-2007_10:06															

144.WCN_MT6631



Schematic design notice of "51_CONNECTIVITY_CONSYS_MT6631"

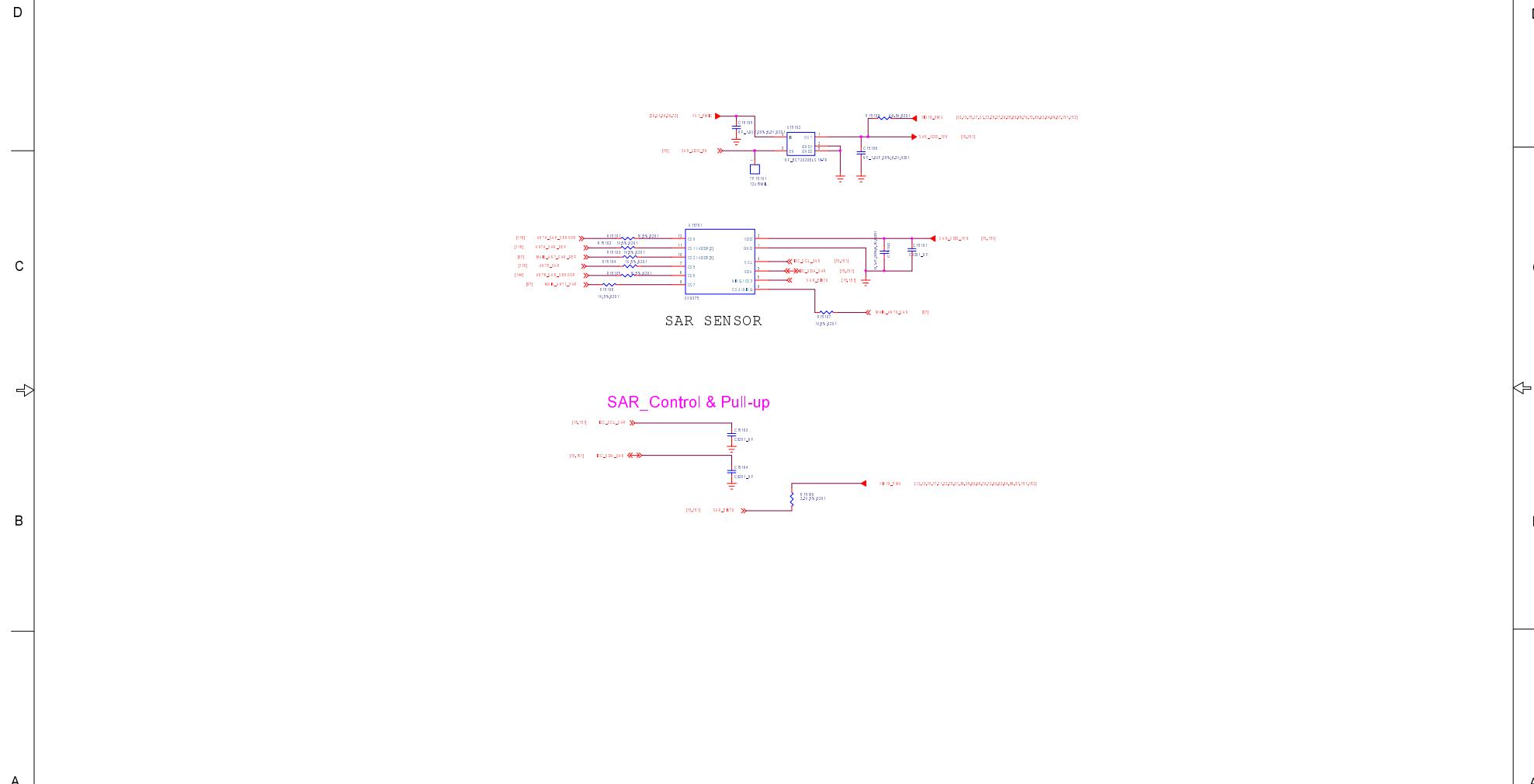
- Note 51-1: For R5015 size, please select 0402 size or larger one
- Note 51-2: Please refer to MT6632 Baseband design notice for VCN33 LDO selection guide
- Note 51-3: If WiFi5G not support, connect pin 34(WIF_RF_S0) to GND
- Note 51-4: Pin 36 (AVDD28_FM) must be connected to VCN28 even if FM not support
- Note 51-5: If WiFi5G were no need, VCN33 could be chosen from PMIC output (VCN33_PMU)

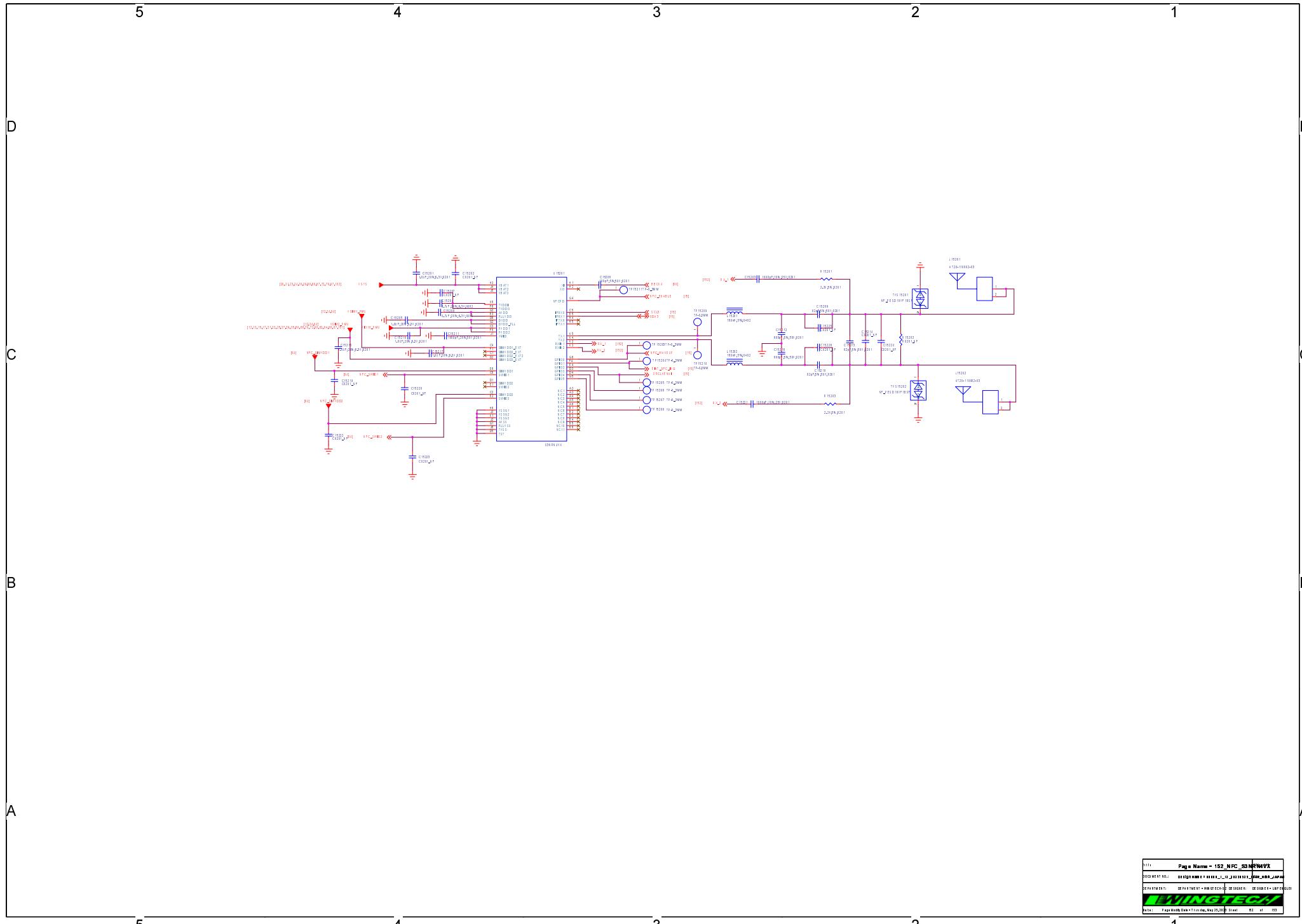
Note: For MT6631 need to configure the VCN33_2_PMU to 1.8V by PMIC SW.

Page Name = 144_WCN_MT6631
Document ID: 00000000000000000000000000000000
Department: DESIGNER + TEST
Date: Friday Date: Thursday, May 25, 2023 Sheet: 14 of 152

REVIEWS		DATE	APPROVED
ITER	DESCRIPTION		
A	INITIAL RELEASE		

151.Sar_sensor





FLASH

